



General Description

The MAX8660/MAX8661 power management ICs (PMICs) power applications processors (APs) in smart cellular phones, PDAs, Internet appliances, and other portable devices.

Four step-down DC-DC outputs, three linear regulators, and an 8th always-on LDO are integrated with powermanagement functions. Two dynamically controlled DC-DC outputs power the processor core and internal memory. Two other DC-DC converters power I/O, memory, and other peripherals. Additional functions include on/off control for outputs, low-battery detection, reset output, and a 2-wire I²C serial interface. The MAX8661 functions the same as the MAX8660, except it lacks the REG1 step-down regulator and the REG7 linear regulator.

All step-down DC-to-DC outputs use fast 2MHz PWM switching and tiny external components. They automatically switch from PWM to high-efficiency, light-load operation to reduce operating current and extend battery life. In addition, a forced-PWM option allows lownoise operation at all loads. Overvoltage lockout protects the device against inputs up to 7.5V.

Applications

PDAs, Palmtops, and Wireless Handhelds

Smart Cell Phones Personal Media Plavers Portable GPS Navigation Digital Cameras

Features

- **Optimized for Marvell PXA3xx and PXA168 Applications Processors**
- ◆ Protected to 7.5V—Shutdown Above 6.3V
- **♦ Four Synchronous Step-Down Converters** REG1, REG2, REG3, REG4
- ♦ Four LDO Regulators REG5, REG6, REG7, REG8
- **♦ 2MHz Switching Allows Small Components**
- ♦ Low, 20µA Deep-Sleep Current
- **♦ Low-Battery Monitor and Reset Output**

Ordering Information

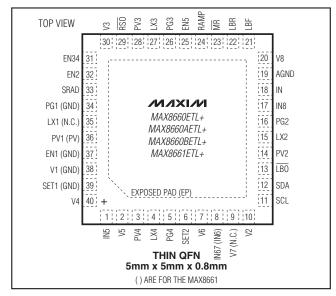
PART	PIN-PACKAGE	OPTIONS
MAX8660ETL+	40 Thin QFN	V1: 3.3V, 3.0V, 2.85V V2: 3.3V, 2.5V, 1.8V V3: 1.4V (default) V4: 1.4V (default)
MAX8660ETL/V+	40 Thin QFN	V1: 3.3V, 3.0V, 2.85V V2: 3.3V, 2.5V, 1.8V V3: 1.4V (default) V4: 1.4V (default)

Note: All devices are specified over the -40°C to 85°C operating temperature range.

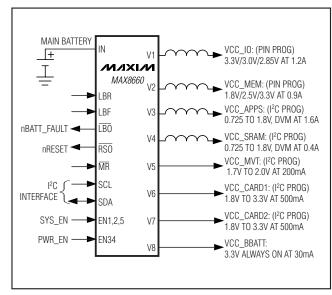
+Denotes lead(Pb)-free/RoHS-compliant package. N denotes an automotive qualified part.

Ordering Information continued at end of data sheet.

Pin Configuration



Simplified Functional Diagram



Maxim Integrated Products 1

Table of C	ontents
General Description	
Applications	1
Features	1
Ordering Information	1
Simplified Functional Diagram	1
Pin Configuration	
Table of Contents	
Absolute Maximum Ratings	4
Electrical Characteristics	4
Typical Operating Characteristics	
Pin Description	
Detailed Description	
Maxim vs. Marvell PXA3xx Terminology	
Step-Down DC-DC Converters (REG1–REG4)	
REG1 (VCC_IO) Step-Down DC-DC Converter (MAX8660 Only)	26
REG2 (VCC_IO, VCC_MEM) Step-Down DC-DC Converters	
REG4 (VCC_SRAM) Step-Down DC-DC Converters	
REG1–REG4 Step-Down DC-DC Converter Operating Modes	
REG1-REG4 Synchronous Rectification	
Linear Regulators (REG5–REG8)	
REG5 (VCC_MVT, VCC_BG, VCC_OSC13M, VCC_PLL)	28
REG6/REG7 (VCC_CARD1, VCC_CARD2)	28
REG8 (VCC_BBATT) Always-On Regulator	
Ramp-Rate Control (RAMP)	
Power Sequencing	29
REG3/REG4 Enable (EN34, EN3, EN4)	29 30
Power Modes	30
Power-Up and Power-Down Timing	30
Voltage Monitors, Reset, and Undervoltage-Lockout Functions	32
Reset Output (RSO) and MR Input	
Low-Battery Detector, (LBO, LBF, LBR)	
Internal Off-Discharge Resistors	
Thermal-Overload Protection	
I ² C Interface	
Data Transfer	
Acknowledge Bit	
Slave Address	35
I ² C Write Operation	36

Table of	f Contents (continued)
Design Procedure	
Setting the Output Voltages	
Inductor Selection	
Input Capacitor Selection	
Output Capacitor Selection	
Applications Information	
Power Dissipation	
PCB Layout and Routing	
Package Marking	
Chip Information	
Package Information	
Tables Table 1 Mayim and Maryell DYA2394 Payer Pamain Tarminalagu	O.F.
Table 1. Maxim and Marvell PXA3xx Power Domain Terminology Table 2. Maxim and Marvell PXA3xx Digital Signal Terminology	
Table 3. SET1 Logic	
Table 4. SET2 Logic	
Table 5. Enable Signals	
Table 6. Truth Table for V3/V4 Enable Logic	
Table 7. Power Modes and Corresponding Quiescent Operating Currents	
Table 8. Internal Off-Discharge Resistor	
Table 9. I ² C Registers	
Table 10. DVM Voltage Change Register (VCC1, 0x20)	
Table 11. Serial Codes for V3 (VCC_APPS) and V4 (VCC_SRAM) Output Volt	
Table 12. Serial Codes for V5 Output Voltage	
Table 13. Serial Codes for V6 and V7 Output Voltages	
Figures	
Figure 1. Example MAX8660 Connection to Marvell PXA3xx Processor	
Figure 2. Functional Diagram	
Figure 3. Typical Applications Circuit	
Figure 4. Soft-Start and Voltage-Change Ramp Rates	
Figure 6. Power Lip Timing	
Figure 6. Power-Up TimingFigure 7. Low-Battery Detector Functional Diagram	
Figure 8. START and STOP Conditions	
Figure 9. Acknowledge Bits	
Figure 10. Slave Address Byte	
Figure 11. Writing to the MAX8660/MAX8661	

ABSOLUTE MAXIMUM RATINGS

IN, IN5, IN6, IN67, EN2, EN34, EN5, \(\overline{LBO} \), \(\overline{RSO} \), \(\overline{MR} \), SET1, SET2, V1, V2, V3, V4, SCL, SDA,	
SRAD to AGND0.3V to +7.5V	
LBF, LBR, EN1, RAMP to AGND0.3V to (V _{IN} + 0.3V)	
V8 to AGND0.3V to (V _{IN8} + 0.3V)	
V5 to AGND0.3V to (V _{IN5} + 0.3V)	
V6, V7 to AGND0.3V to $(V_{IN67} + 0.3V)$	
PV1 to PG10.3V to +7.5V	
PV2 to PG20.3V to +7.5V	
PV3 to PG30.3V to +7.5V	
PV4 to PG40.3V to +7.5V	
PV, PV1, PV2, PV3, PV4, IN8 to IN0.3V to +0.3V	
LX1 Continuous RMS Current (Note 1)2.3A	

LX2 Continuous RMS Current (Note 1)	2.0A
LX3 Continuous RMS Current (Note 1)	
LX4 Continuous RMS Current (Note 1)	
PG1, PG2, PG3, PG4, EP to AGND	0.6V to +0.6V
GND to AGND	0.3V to +0.3V
All REGx Output Short-Circuit Duration	Continuous
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
40-Pin Thin QFN (derate 35.7mW/°C above	+70°C)2857mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	+300°C

Note 1: LX_ has internal clamp diodes to PG_ and PV_. Applications that forward bias these diodes must take care not to exceed the IC's package power-dissipation limits.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_A = -40$ °C to +85°C, unless otherwise noted. Typical values are at $T_A = +25$ °C.) (Note 2)

PARAMETER	SYMBOL	C	CONDITIONS	MIN	TYP	MAX	UNITS
PV1, PV2, PV3, PV4, IN, IN8 Supply Voltage Range	V _{IN}	PV1, PV2, PV3, PV connected together	/4, IN, and IN8 must be er externally	2.6		6.0	V
IN Undervoltage-Lockout	V o	V _{IN} rising		2.250	2.400	2.550	V
Threshold	V _U VLO	V _{IN} falling		2.200	2.350	2.525	\ \ \
IN Overvoltage-Lockout	Vovuo	V _{IN} rising		6.20	6.35	6.50	<u> </u>
Threshold	V _{OVLO}	V _{IN} falling		6.00	6.15	6.30	V
			Only V8 on (deep-sleep power mode)		20		
Input Current		No load; SDA = SCL = V8	V1, V2, and V8 on; V1 and V2 in normal (skip) operating mode		50		
	l _{IN} + l _{PV1} +l _{PV2} +		V1, V2, V5, and V8 on (sleep power mode); V1 and V2 in normal (skip) operating mode		90		
	I _{PV3} +I _{PV4} + I _{IN5} + I _{IN67} + I _{IN8}		V1, V2, V3, V4, V5, and V8 on (run power mode); V1, V2, V3, and V4 in normal (skip) operating mode		140		μА
			V1, V2, V3, V4, V5, V6, V7, and V8 (all on); V1, V2, V3, and V4 in normal (skip) operating mode		250		
		Undervoltage lock	$V_{IN} = 2.2V$		1.5]
		Overvoltage locko	out, V _{IN} = 6.5V		25		

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_{A} = -40$ °C to +85°C, unless otherwise noted. Typical values are at $T_{A} = +25$ °C.) (Note 2)

PARAMETER	SYMBOL	CONE	DITIONS	MIN	TYP	MAX	UNITS
PWM Switching Frequency	fsw			1.9	2.0	2.1	MHz
REG1—SYNCHRONOUS STEP-D	OWN DC-DC	CONVERTER (MAX8	660, MAX8660A only)				•
		SET1 = IN, V _{PV1} = 4.3	2V, load = 600mA	3.250	3.300	3.350	
V1 Voltage Accuracy (MAX8860/MAX8860B)	V1	SET1 not connected, load = 600mA	$V_{PV1} = 3.6V,$	2.955	3.000	3.045	V
		SET1 = AGND, V _{PV1}	= 3.6V, load = 600mA	2.807	2.850	2.893	
		SET1 = IN, $V_{PV1} = 4.3$		2.463	2.500	2.538	
V1 Voltage Accuracy (MAX8660A)	V1	SET1 not connected,		1.970	2.000	2.030	V
		SET1 = AGND, 3.6V,	load = 600mA	1.773	1.800	1.827	
V1 Load Regulation		Load = 0 to 1200mA			-1.5		%/A
V1 Line Regulation					0.15		%/V
SET1 Input Leakage Current					0.01		μΑ
V1 Dropout Voltage		Load = 800mA (Note	s 3, 4)		150		mV
Vi Diopout Voltage		Load = 1200mA (Not	es 3, 4)		200		IIIV
p-Channel On-Resistance					0.12		Ω
n-Channel On-Resistance					0.15		Ω
p-Channel Current-Limit Threshold				1.5	1.8	2.2	А
n-Channel Zero-Crossing Threshold					25		mA
n-Channel Negative Current Limit		Forced-PWM mode of	inly		-975		mA
REG1 Maximum Output Current	I _{OUT1}	2.6V ≤ V _{PV1} ≤ 6V (No	te 5)	1.2			Α
V1 Bias Current		,	•		5		μΑ
LX1 Leakage Current		V _{PV1} = 6V, LX1 = PG1 or PV1,	T _A = +25°C	-2	±0.03	+2	μΑ
EXT Educage durient		$V_{EN1} = 0V$	T _A = +85°C		±0.2		μ, τ
Soft-Start Ramp Rate (MAX8660/MAX8860B)		To V1 = 3.3V (total ra all V1 output voltages		5	7	9	mV/μs
Soft-Start Ramp Rate (MAX8660A)		To V1 = 2.5V (total ramp time is 450µs for all V1 output voltages)		3	5	7	mV/μs
V5 to V1 Enable Time	tvmHvSH1	Figure 6			350		μs
Internal Off-Discharge Resistance					650		Ω
Minimum Duty Cycle		Forced-PWM mode of skip mode is 0%	nly, min duty cycle in		16.7		%
Maximum Duty Cycle					100		%

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 2)

PARAMETER	SYMBOL	COND	OITIONS	MIN	TYP	MAX	UNITS
REG2—SYNCHRONOUS STEP-DC	WN DC-DC	CONVERTER					
		SET2 = IN, V _{PV2} = 4.2	2V, load = 600mA	3.250	3.300	3.350	
V2 Voltage Accuracy (MAX8660/MAX8860B)	V2	SET2 not connected, load = 600mA	V _{PV2} = 3.6V,	2.463	2.500	2.538	V
		SET2 = AGND, V _{PV2} :	= 3.6V, load = 600mA	1.773	1.800	1.827	
		SET2 = IN, V _{PV2} = 4.2	2V, load = 600mA	2.463	2.500	2.538	
V2 Voltage Accuracy (MAX8660A)	V2	SET2 not connected, load = 600mA	V _{PV2} = 3.6V,	1.970	2.000	2.030	V
		SET2 = AGND, V _{PV2} :	= 3.6V, load = 600mA	1.773	1.800	1.827	
V2 Load Regulation		Load = 0 to 900mA			-1.7		%/A
V2 Line Regulation					0.15		%/V
SET2 Input Leakage Current					0.01		μΑ
V2 Dropout Voltage		Load = 900mA (Notes	s 3, 4)		225		mV
p-Channel On-Resistance					0.18		Ω
n-Channel On-Resistance					0.15		Ω
p-Channel Current-Limit Threshold				1.10	1.30	1.50	А
n-Channel Zero Crossing Threshold					25		mA
n-Channel Negative Current Limit		Forced-PWM mode o	nly		-800		mA
REG2 Maximum Output Current	I _{OUT2}	2.6V ≤ V _{PV2} ≤ 6V (Not	te 5)	0.9			А
V2 Bias Current		,	·		5		μΑ
LX2 Leakage Current		$V_{PV2} = 6V$, LX2 = PG2 or PV2,	T _A = +25°C	-2	±0.03	+2	μA
•		$V_{EN2} = 0V$	$T_A = +85^{\circ}C$		0.2		
Soft-Start Ramp Rate		To V2 = 1.8V (total rail V2 output voltages		2	4	6	mV/μs
V5 to V2 Enable Time	tvmHvSH2	Figure 6			350		μs
Internal Off-Discharge Resistance					650		Ω
Minimum Duty Cycle		Forced-PWM mode of skip mode is 0%	nly; min duty cycle in		16.7		%
Maximum Duty Cycle					100		%
REG3—SYNCHRONOUS STEP-DO	WN DC-DC	CONVERTER					
V3 Output Voltage Accuracy		MAX8860/MAX8660A default output voltage load = 600mA	$P_{V3} = 3.6V$	1.379	1.400	1.421	V
	V3	MAX8860B REG3 def V _{PV3} = 3.6V, load = 6		1.133	1.150	1.167	=
		REG3 serial programmer load = 600mA (Note 6	med from 0.9V to 1.8V, 6)	-1.5		+1.5	%
V3 Load Regulation		Load = 0 to 1600mA			-17		mV/A
V3 Line Regulation		(Note 7)			0.05		%/V
p-Channel On-Resistance					0.12		Ω
n-Channel On-Resistance					0.08		Ω

6 ______ /N/XI/M

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_{A} = -40^{\circ}$ C to $+85^{\circ}$ C, unless otherwise noted. Typical values are at $T_{A} = +25^{\circ}$ C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	3	MIN	TYP	MAX	UNITS
p-Channel Current-Limit Threshold				1.85	2.15	2.45	А
n-Channel Zero-Crossing Threshold					25		mA
n-Channel Negative Current Limit		Forced-PWM mode only			-0.8		А
REG3 Maximum Output Current	lout3	2.6V ≤ V _{PV3} ≤ 6V (Note 5)		1.6			Α
V3 Bias Current					0.01		μΑ
LX3 Leakage Current		$V_{PV3} = 6V, LX3 = PG3 \text{ or}$	$T_A = +25$ °C	-2	+0.03	+2	μΑ
EXO Edakage Guiterii		PV3, V _{EN34} = 0V	T _A = +85°C		0.24		μπ
Soft-Start Ramp Rate		MAX8660/MAX8660A/MAX86 56kΩ to 1.4V	661, R _{RAMP} =		8		mV/µs
·		MAX8660B, R _{RAMP} = 56 k Ω t	to 1.15V		6.7] '
V3 Dynamic-Change Ramp Rate		$R_{RAMP} = 56k\Omega$			10		mV/μs
FNOA L VO F LLL T		MAX8660/MAX8660A/MAX80 up to 1.4V, Figure 6, R _{RAMP} =			400		
EN34 to V3 Enable Time	tPHLVTH3	MAX8660B, powering up to 1 $R_{RAMP} = 56k\Omega$.15V, Figure 6,		400		μs
Internal Off-Discharge Resistance					550		Ω
Minimum Duty Cycle		Forced-PWM mode only, mir skip mode is 0%	n duty cycle in		16.7		%
Maximum Duty Cycle					100		%
REG4—SYNCHRONOUS STEP-DO	WN DC-DC	CONVERTER					
		MAX8660/MAX8660A/MAX8661 REG4 default output voltage, VPV4 = 3.6V, load = 200mA		1.379	1.400	1.421	V
V4 Output Voltage Accuracy	V4	MAX8660B REG4 default output voltage, VPV4 = 3.6V, load = 200mA		1.133	1.150	1.167	V
		REG4 serial programmed fro load = 200mA (Note 6)	om 0.9V to 1.8V,	-1.5		+1.5	%
V4 Load Regulation		Load = 0 to 400mA			-40		mV/A
V4 Line Regulation		(Note 7)			0.1		%/V
p-Channel On-Resistance					0.37		Ω
n-Channel On-Resistance					0.3		Ω
p-Channel Current-Limit Threshold				0.05	0.78	0.90	А
n-Channel Zero-Crossing Threshold					25		mA
n-Channel Negative Current Limit		Forced-PWM mode only			-975		mA
REG4 Maximum Output Current	lout4	2.6V ≤ V _{PV4} ≤ 6V (Note 5)		0.4			А
V4 Bias Current					0.01		μΑ
LX4 Leakage Current		V _{PV4} = 6V, LX4 = PG4 or PV4, V _{EN34} = 0V	T _A = +25°C T _A = +85°C	-2	±0.02	+2	μΑ
Soft Start Damp Data		MAX8660/MAX8660A/MAX8661, $R_{RAMP} = 56kΩ$ to 1.4V					m\//uc
Soft-Start Ramp Rate				6.7		mV/µs	
V4 Dynamic-Change Ramp Rate		$R_{RAMP} = 56k\Omega$			10		mV/μs

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_A = -40^{\circ}$ C to $+85^{\circ}$ C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}$ C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ENO4 to 1/4 Enoble Time		MAX8660/MAX8660A/MAX8661, powering up to 1.4V, Figure 6, R_{RAMP} = 56k $Ω$		400		
EN34 to V4 Enable Time	[†] PHLVTH4	MAX8660B, powering up to 1.15V, Figure 6, $R_{RAMP} = 56k\Omega$		400		μs
Internal Off-Discharge Resistance				550		Ω
Minimum Duty Cycle		Forced-PWM mode only, minimum duty cycle in skip mode is 0%		16.7		%
Maximum Duty Cycle				100		%
REG5 LDO						
IN5 Input Voltage Range	V _{IN5}		2.35		V _{IN}	V
V5 Output Voltage	V5	REG5 default output voltage, $2.35V \le V_{IN5} \le 6V$, load = 0 to 200mA	1.764	1.800	1.836	V
vo Output voltage	٧٥	REG5 serial programmed from 1.7V to 2.0, $2.35V \le V_{\text{IN5}} \le 6V$, load = 0 to 200mA	-2		+2	%
V5 Output Current Limit	I _{OUT5}		225	350	500	mA
V5 Output-Voltage Noise		10Hz to 100kHz, I _{OUT5} = 10mA		160		μVRMS
V5 Power-Supply Rejection		$V_{IN5} = (V5 + 1V), I_{OUT5} = 10mA, f = 10kHz$		40		dB
V5 Soft-Start Ramp Rate		Powering up to 1.8V (total ramp time is 225µs for all V5 output voltages)	5	7	9	mV/µs
EN5 to V5 Enable Time	tsehvmh	Figure 6		290		μs
V5 Dynamic-Change Ramp Rate		$R_{RAMP} = 56k\Omega$		10		mV/µs
Internal Off-Discharge Resistance				2		kΩ
REG6, REG7 LDOs	•					
IN67 Input Voltage Range	VIN67		2.35		VIN	V
REG6 and REG7 Output Voltage (POR Default to 0V, Set by Serial Input)	V6 V7	Setting from 1.8V to 3.3V in 0.1V steps, load = 0 to 300mA	-3		+3	%
V6, V7 Dropout Voltage		3V mode, load = 300mA (Note 3)		55	100	mV
V6, V7 Output Current Limit	IOUT6 IOUT7	V _{IN67} = 3.6V		750		mA
V6, V7 Soft-Start Ramp Rate		Powering up to 3.3V, (total ramp time is 450µs for all V6/V7 output voltages)	5	7	9	mV/µs
Internal Off-Discharge Resistance				350		Ω
REG8 ALWAYS-ON LDO						
V(2, C, 1, 1, V, I)	1.0	Load = 0 to 15mA	3.168	3.300	3.432	, ,
V8 Output Voltage	V8	Load = 30mA	2.800	3.2	3.432	V
V8 Dropout Voltage		Load = 15mA (Note 3)		180		mV
V8 Output Current Limit	I _{OUT8}	V8 = 2.5V	30	70	135	mA
Internal Off-Discharge Resistance				1.5		kΩ
LOW-BATTERY DETECTOR (LBF	, LBR, LBO)					
Low-Battery Falling Threshold	V _{LBFTH}		1.182	1.200	1.218	V
Low-Battery Rising Threshold	V _{LBRTH}		1.231	1.250	1.268	V
<u> </u>	l					L

8 ______ /N/XI/N

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_A = -40^{\circ}$ C to $+85^{\circ}$ C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}$ C.) (Note 2)

LBO, RSO Output-High Leakage Current V _{IN} = 6V, T _A = +25°C 0.2 μA LBO Output Low Level 2.60 ≤ V _{IN} ≤ 6V, sinking 3mA 0.2 V VIN = 1V, sinking 100µA 0.4 V Minimum V _{IN} for LBO Assertion LBO is forced low when the device is in UVLO 1 V LBF and LBR Input Bias Current Figure 6 0 3 μps LBF and LBR Input Bias Current Ta = +25°C -50 0 +50 nA RESET (MR, RSO) Ta = +85°C -50 0 +50 nA RSO Dassesert Delay 1/8HRSTH Figure 6 20 24 28 ms RSO Output-High Leakage VRHRSTH Figure 6 20 24 28 ms RSO Output-Low Level Pigure 6 20 24 28 ms RSO Output-Ligh Leakage VIN = 6V, Ta = +25°C 20 24 28 ms RSO Output-Ligh Leakage 26/5 ≤ Vin ≤ 6V. Sinking 3mA 0.2 2 2 3 V Minimum Vin for RSO Assertion	PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			V _{IN} = 6V, T _A = +25°C			0.2	μА
Vin = TV, sinking 100µA			2.6V ≤ V _{IN} ≤ 6V, sinking 3mA			0.2	
UVLO	LBO Output Low Level		V _{IN} = 1V, sinking 100μA			0.4	T V
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Minimum V _{IN} for LBO Assertion			1			V
$ \begin{array}{ c c c c c c } \hline RA = +85^{\circ}C & 0.5 & 0.8 \\ \hline RESET (MR, RSO) \\ \hline RSO Threshold & VRSOTH & Voltage on V8, falling, hysteresis is 5% (typ) & 2.1 & 2.2 & 2.3 & V \\ RSO Deassert Delay & IV_DHRSTH & Figure 6 & 20 & 24 & 28 & ms \\ RSO Output-High Leakage & VIN = 6V, T_A = +25^{\circ}C & 0.2 & 24 & 28 & ms \\ \hline RSO Output Low Level & 2.6V \le VIN \le 6V, sinking 3mA & 0.2 & V \\ \hline MINIMUM VIN for RSO Assertion & RSO is forced low when the device is in UVLO & 0.4 & V \\ \hline MR Input High Level & 2.6V \le VIN \le 6V & 1.4 & V \\ \hline MR Input Leakage Current & VIN = 6V, T_A = +25^{\circ}C & 0.2 & +0.2 & \muA \\ \hline MR Minimum Pulse Width & IMR & 1 & 1 & \mus \\ \hline THERMAL-OVERLOAD PROTECTION & 1.5 & 0.5 \\ \hline THERMAL-OVERLOAD PROTECTION & 1.5 & 0.5 \\ \hline ENDIS Input Leakage Current & Tyrising & +160 & 0.5 \\ \hline ENDIS Input Leakage Current & 2.6V \le VIN \le 6V & 1.4 & V \\ \hline ENDIS Input Leakage Current & Tyrising & +160 & 0.5 \\ \hline ENDIS Input Leakage Current & 2.6V \le VIN \le 6V & 1.4 & V \\ \hline ENDIS Input Leakage Current & 2.6V \le VIN \le 6V & 1.4 & V \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input Leakage Current & 0.5 & 0.5 & 0.5 & 0.5 \\ \hline ENDIS CL, SDA Input Low Voltage & 0.4 & V \\ \hline SCL, SDA Input Low Voltage & 0.4 & V \\ \hline SCL, SDA Input Low Voltage & 0.4 & V \\ \hline SCL, SDA Input Current & 0.5 & 0.5 & 0.5 \\ \hline ENDIS Input High Level & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Voltage & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline SRAD Input Low Velevel & 0.6V \le VIN \le 6V, SINKING 3mA & 0.2 & V \\ \hline $	LBO Deassert Delay	tvbhbfh	Figure 6	0	3		μs
TA = +85°C 0.5 RESET (MR, RSO) RSO Threshold VRSOTH Voltage on V8, falling, hysteresis is 5% (typ) 2.1 2.2 2.3 V RSO Deassert Delay VBHRSTH Figure 6 20 24 28 ms RSO Output-High Leakage VIN = 6V, TA = +25°C 0.2 µA RSO Output-Low Level 2.6V ≤ VIN ≤ 6V, sinking 3mA 0.2 V Minimum VIN for RSO Assertion RSO is forced low when the device is in UVLO 1 V MR Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V MR Input Low Level 2.6V ≤ VIN ≤ 6V 1.4 V MR Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 µA MR Minimum Pulse Width t _{MR} 1 µs THERMAL-OVERLOAD PROTECTION Thermal-Shutdown Temperature Ty rising +160 °C ENABLE INPUTS (EN1, EN2, EN34, EN5) EN_ Input Leakage Current 2.6V ≤ VIN ≤ 6V 1.4 V EN_ Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 µA WR Input Leakage Current Ty rising +160 °C ENABLE INPUTS (EN1, EN2, EN34, EN5) EN_ Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V EN_ Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 µA WE CLOSIC (SDA, SCL, SRAD) SCL, SDA Input High Voltage 1.4 V SCL, SDA Input Low Voltage 1.4 V SCL, SDA Input High Voltage 0.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Voltage 0.4 V SCL, SDA Input High Voltage 0.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V SCL, SDA Input High Level 2.6V ≤ VIN ≤ 6V 1	LDE		T _A = +25°C	-50	0	+50	A
RSO Threshold VRSOTH Voltage on V8, falling, hysteresis is 5% (typ) 2.1 2.2 2.3 V RSO Deassert Delay tyBHRSTH Figure 6 20 24 28 ms RSO Output-High Leakage VIN = 6V, TA = +25°C 20 24 28 ms RSO Output-Low Level 2.6V ≤ VIN ≤ 6V, sinking 3mA 0.2 V Minimum VIN for RSO Assertion RSO is forced low when the device is in UVLO 1.4 V MR Input High Level 2.6V ≤ VIN ≤ 6V 1.4 V MR Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 µA MR Minimum Pulse Width t _{MR} 1 µs THERMAL-OVERLOAD PROTECTION T ₁ rising +160 °C Thermal-Shutdown Temperature T ₂ rising +160 °C Thermal-Shutdown Temperature T ₃ rising +160 °C Thermal-Shutdown Temperature T ₄ rising +160 °C Thermal-Sh	LBF and LBR Input Blas Current 		T _A = +85°C		0.5		nA
RSO Deassert Delay tvBHRSTH Figure 6 20 24 28 ms RSO Output-High Leakage Current VIN = 6V, TA = +25°C 0.2 μA RSO Output Low Level 2.6 ∨ ≤ VIN ≤ 6V, sinking 3mA 0.2 V Minimum VIN for RSO Assertion RSO is forced low when the device is in UVLO 1 V MR Input High Level 2.6 ∨ ≤ VIN ≤ 6V 1.4 V MR Input Low Level 2.6 ∨ ≤ VIN ≤ 6V 0.4 V MR Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 μA MR Minimum Pulse Width ttm 1 μs THERMAL-OVERLOAD PROTECTION Thermal-Shutdown Temperature T Jr ising +160 °C Thermal-Shutdown Hysteresis 15 °C EN_ Input High Level 2.6 ∨ ≤ VIN ≤ 6V 1.4 V V EN_ Input Low Level 2.6 ∨ ≤ VIN ≤ 6V 0.4 V EN_ Input Leakage Current VIN = 6V, TA = +25°C -0.2 +0.2 μA PC LOGIC (SDA, SCL, SRAD) VIN = 6V, TA = +25°C -0.2 +0.2 μA	RESET (MR, RSO)						
RSO Output-High Leakage Current VIN = 6V, TA = +25°C 0.2	RSO Threshold	VRSOTH	Voltage on V8, falling, hysteresis is 5% (typ)	2.1	2.2	2.3	V
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	RSO Deassert Delay	tvbhrsth	Figure 6	20	24	28	ms
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{IN} = 6V, T _A = +25°C			0.2	μΑ
V _{IN} = 1V, sinking 100μA 0.4	700		2.6V ≤ V _{IN} ≤ 6V, sinking 3mA			0.2	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	RSO Output Low Level		V _{IN} = 1V, sinking 100µA			0.4	j ^v
$\begin{array}{ c c c c c } \hline \text{MR} \ \text{Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 0.4 & V \\ \hline \hline \text{MR} \ \text{Input Leakage Current} & V_{\text{IN}} = 6V, T_{\text{A}} = +25^{\circ}\text{C} & -0.2 & +0.2 & \mu \text{A} \\ \hline \hline \text{MR} \ \text{Minimum Pulse Width} & t_{\text{MR}} & 1 & \mu \text{s} \\ \hline \hline \textbf{THERMAL-OVERLOAD PROTECTION} \\ \hline \hline \textbf{Thermal-Shutdown Temperature} & T_{\text{J}} \ \text{rising} & +160 & ^{\circ}\text{C} \\ \hline \textbf{Thermal-Shutdown Hysteresis} & 15 & ^{\circ}\text{C} \\ \hline \textbf{ENABLE INPUTS (EN1, EN2, EN34, EN5)} \\ \hline \textbf{EN_Input High Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{EN_Input Leakage Current} & V_{\text{IN}} = 6V, T_{\text{A}} = +25^{\circ}\text{C} & -0.2 & +0.2 & \mu \text{A} \\ \hline \textbf{PC LOGIC (SDA, SCL, SRAD)} \\ \hline \textbf{SCL, SDA Input High Voltage} & 1.4 & V \\ \hline \textbf{SCL, SDA Input Hysteresis} & 0.1 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Hysteresis} & 0.1 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \textbf{SCL, SDA Input Low Voltage} & 2.6V \le V_{\text{IN}} \le 6V, \text{ sinking 3mA} & 0.2 & V \\ \hline \textbf{SRAD Input High Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V & 1.4 & V \\ \hline \textbf{SRAD Input Low Level} & 2.6V \le V_{\text{IN}} \le 6V $	Minimum V _{IN} for RSO Assertion			1			V
$\begin{array}{ c c c c c } \hline{\text{MR}} \ \text{Input Leakage Current} & V_{IN} = 6V, T_{A} = +25^{\circ}C & -0.2 & +0.2 & \mu A \\ \hline{\text{MR}} \ \text{Minimum Pulse Width} & t_{MR} & & & & 1 & & \mu s \\ \hline \hline{\textbf{THERMAL-OVERLOAD PROTECTION} \\ \hline \hline{\textbf{Thermal-Shutdown Temperature}} & T_{J} \ \text{rising} & +160 & ^{\circ}C \\ \hline \hline{\textbf{Thermal-Shutdown Hysteresis}} & & & 15 & ^{\circ}C \\ \hline \hline{\textbf{ENABLE INPUTS (EN1, EN2, EN34, EN5)}} \\ \hline EN_{L} \ \text{Input High Level} & 2.6V \leq V_{IN} \leq 6V & 1.4 & V \\ \hline \text{EN_{L} Input Leakage Current}} & V_{IN} = 6V, T_{A} = +25^{\circ}C & -0.2 & +0.2 & \mu A \\ \hline \textbf{PC LOGIC (SDA, SCL, SRAD)} \\ \hline \text{SCL, SDA Input Ligh Voltage} & 1.4 & V \\ \hline \text{SCL, SDA Input Low Voltage} & 1.4 & V \\ \hline \text{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \text{SCL, SDA Input Low Voltage} & 0.4 & V \\ \hline \text{SCL, SDA Input Current}} & T_{A} = +25^{\circ}C, IN = AGND, V_{IN} = 6V & -10 & +10 & \mu A \\ \hline \text{SDA Output Low Voltage}} & 2.6V \leq V_{IN} \leq 6V, \text{sinking 3mA} & 0.2 & V \\ \hline \text{SRAD Input High Level}} & 2.6V \leq V_{IN} \leq 6V & 1.4 & V \\ \hline \text{SRAD Input Low Level}} & 2.6V \leq V_{IN} \leq 6V & 1.4 & V \\ \hline \end{array}$	MR Input High Level		2.6V ≤ V _{IN} ≤ 6V	1.4			V
$\begin{tabular}{ c c c c c } \hline{MR} & Minimum Pulse Width & t_{MR} & 1 & \mus \\ \hline \hline{\textbf{THERMAL-OVERLOAD PROTECTION} \\ \hline \hline Thermal-Shutdown Temperature & T_J rising & +160 & ^C \\ \hline Thermal-Shutdown Hysteresis & 15 & ^C \\ \hline \hline \textbf{ENABLE INPUTS (EN1, EN2, EN34, EN5)} \\ \hline EN_I Input High Level & 2.6V \le V_{IN} \le 6V & 1.4 & V \\ \hline EN_I Input Low Level & 2.6V \le V_{IN} \le 6V & 0.4 & V \\ \hline EN_I Input Leakage Current & V_{IN} = 6V, T_A = +25^{\circ}C & -0.2 & +0.2 & \muA \\ \hline \textbf{PC LOGIC (SDA, SCL, SRAD)} \\ \hline SCL, SDA Input High Voltage & 1.4 & V \\ \hline SCL, SDA Input Low Voltage & 0.4 & V \\ \hline SCL, SDA Input Hysteresis & 0.1 & V \\ \hline SCL, SDA Input Current & T_A = +25^{\circ}C, IN = AGND, V_{IN} = 6V & -10 & +10 & \muA \\ \hline SDA Output Low Voltage & 2.6V \le V_{IN} \le 6V, sinking 3mA & 0.2 & V \\ \hline SRAD Input High Level & 2.6V \le V_{IN} \le 6V & 1.4 & V \\ \hline SRAD Input Low Level & 2.6V \le V_{IN} \le 6V & 0.4 & V \\ \hline SRAD Input Low Level & 2.6V \le V_{IN} \le 6V & 0.4 & V \\ \hline SRAD Input Low Level & 2.6V \le V_{IN} \le 6V & 0.4 & V \\ \hline SRAD Input Low Level & 2.6V \le V_{IN} \le 6V & 0.4 & V \\ \hline \end{tabular}$	MR Input Low Level		$2.6V \le V_{IN} \le 6V$			0.4	V
THERMAL-OVERLOAD PROTECTION Thermal-Shutdown Temperature TJ rising +160 °C Thermal-Shutdown Hysteresis 15 °C ENABLE INPUTS (EN1, EN2, EN34, EN5) EN_ Input High Level 2.6V ≤ V _{IN} ≤ 6V 1.4 V EN_ Input Low Level 2.6V ≤ V _{IN} ≤ 6V 0.4 V EN_ Input Leakage Current V _{IN} = 6V, TA = +25°C -0.2 +0.2 μA PC LOGIC (SDA, SCL, SRAD) SCL, SDA Input High Voltage 1.4 V SCL, SDA Input High Voltage 1.4 V SCL, SDA Input Low Voltage 0.4 V SCL, SDA Input Hysteresis 0.1 V SCL, SDA Input Ucurrent TA = +25°C, IN = AGND, V _{IN} = 6V -10 +10 μA SDA Output Low Voltage 2.6V ≤ V _{IN} ≤ 6V, sinking 3mA 0.2 V SRAD Input High Level 2.6V ≤ V _{IN} ≤ 6V 1.4 V SRAD Input Low Level 2.6V ≤ V _{IN} ≤ 6V 0.4 V	MR Input Leakage Current		$V_{IN} = 6V, T_A = +25^{\circ}C$	-0.2		+0.2	μΑ
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	MR Minimum Pulse Width	t _{MR}			1		μs
Thermal-Shutdown Hysteresis	THERMAL-OVERLOAD PROTEC	TION					
ENABLE INPUTS (EN1, EN2, EN34, EN5) EN_ Input High Level	Thermal-Shutdown Temperature		T _J rising		+160		°C
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Thermal-Shutdown Hysteresis				15		°C
EN_ Input Low Level $2.6V \le V_{IN} \le 6V$ 0.4 V EN_ Input Leakage Current $V_{IN} = 6V$, $T_A = +25^{\circ}C$ -0.2 $+0.2$ μ APC LOGIC (SDA, SCL, SRAD)SCL, SDA Input High Voltage 1.4 V SCL, SDA Input Low Voltage 0.4 V SCL, SDA Input Hysteresis 0.1 V SCL, SDA Input Current V V SCL, SDA Input Current V V SDA Output Low Voltage V V SRAD Input High Level V V SRAD Input Low Level V V SRAD Input Low Level V V	ENABLE INPUTS (EN1, EN2, EN3	34, EN5)					
EN_ Input Leakage Current $V_{IN} = 6V$, $T_A = +25^{\circ}C$ -0.2+0.2μAPC LOGIC (SDA, SCL, SRAD)SCL, SDA Input High Voltage1.4VSCL, SDA Input Low Voltage0.4VSCL, SDA Input Hysteresis0.1VSCL, SDA Input Current $T_A = +25^{\circ}C$, $IN = AGND$, $V_{IN} = 6V$ -10+10 μA SDA Output Low Voltage $2.6V \le V_{IN} \le 6V$, sinking 3mA0.2VSRAD Input High Level $2.6V \le V_{IN} \le 6V$ 1.4VSRAD Input Low Level $2.6V \le V_{IN} \le 6V$ 0.4V	EN_ Input High Level		$2.6V \le V_{IN} \le 6V$	1.4			V
PC LOGIC (SDA, SCL, SRAD)SCL, SDA Input High Voltage1.4VSCL, SDA Input Low Voltage0.4VSCL, SDA Input Hysteresis0.1VSCL, SDA Input Current $T_A = +25^{\circ}C$, $IN = AGND$, $V_{IN} = 6V$ -10+10 μA SDA Output Low Voltage $2.6V \le V_{IN} \le 6V$, sinking 3mA0.2VSRAD Input High Level $2.6V \le V_{IN} \le 6V$ 1.4VSRAD Input Low Level $2.6V \le V_{IN} \le 6V$ 0.4V	EN_ Input Low Level		$2.6V \le V_{IN} \le 6V$			0.4	V
SCL, SDA Input High Voltage1.4VSCL, SDA Input Low Voltage0.4VSCL, SDA Input Hysteresis0.1VSCL, SDA Input Current $T_A = +25^{\circ}C$, $IN = AGND$, $V_{IN} = 6V$ -10+10 μA SDA Output Low Voltage $2.6V \le V_{IN} \le 6V$, sinking 3mA0.2VSRAD Input High Level $2.6V \le V_{IN} \le 6V$ 1.4VSRAD Input Low Level $2.6V \le V_{IN} \le 6V$ 0.4V	EN_ Input Leakage Current		$V_{IN} = 6V, T_A = +25^{\circ}C$	-0.2		+0.2	μΑ
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	I ² C LOGIC (SDA, SCL, SRAD)						
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	SCL, SDA Input High Voltage			1.4			V
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	SCL, SDA Input Low Voltage					0.4	V
SDA Output Low Voltage $2.6V \le V_{\text{IN}} \le 6V$, sinking 3mA 0.2 VSRAD Input High Level $2.6V \le V_{\text{IN}} \le 6V$ 1.4 VSRAD Input Low Level $2.6V \le V_{\text{IN}} \le 6V$ 0.4 V	SCL, SDA Input Hysteresis				0.1		V
SRAD Input High Level $2.6V \le V_{\text{IN}} \le 6V$ 1.4VSRAD Input Low Level $2.6V \le V_{\text{IN}} \le 6V$ 0.4V	SCL, SDA Input Current		$T_A = +25$ °C, $IN = AGND$, $V_{IN} = 6V$	-10		+10	μΑ
SRAD Input Low Level $2.6V \le V_{\text{IN}} \le 6V$ 0.4 V	SDA Output Low Voltage		$2.6V \le V_{IN} \le 6V$, sinking 3mA			0.2	V
<u> </u>	SRAD Input High Level		$2.6V \le V_{ N} \le 6V$	1.4			V
SRAD Input Leakage Current $V_{IN} = 6V$, $T_A = +25^{\circ}C$ -0.2 $+0.2$ μA	SRAD Input Low Level		2.6V ≤ V _{IN} ≤ 6V			0.4	V
	SRAD Input Leakage Current		$V_{IN} = 6V, T_A = +25^{\circ}C$	-0.2		+0.2	μA

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{IN5} = V_{IN67} = V_{IN8} = 3.6V$, Figure 3, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
I ² C TIMING	JI.	,				
Clock Frequency	fscl				400	kHz
Hold Time (Repeated) START Condition	thd;sta	Figure 8	0.6			μs
CLK Low Period	tLOW		1.3			μs
CLK High Period	thigh		0.6			μs
Set-Up Time for a Repeated START Condition	tsu;sta	Figure 8	0.6			μs
DATA Hold Time	thd;dat	Figure 9	0			μs
DATA Set-Up Time	tsu;dat	Figure 9	100			ns
Set-Up Time for STOP Condition	tsu;sto	Figure 8	0.6			μs
Bus-Free Time Between STOP and START	tBUF		1.3			μs
Maximum Pulse Width of Spikes that Must Be Suppressed by the Input Filter of Both DATA and CLK Signals				50		ns

- **Note 2:** Limits are 100% production tested at T_A = +25°C. Limits over the operating temperature range are guaranteed through correlation using statistical quality control (SQC) methods.
- Note 3: The dropout voltage is defined as V_{IN} V_{OUT} when V_{OUT} is 100mV below the nominal value of V_{OUT}.
- Note 4: Dropout voltage (V_{DO}) is a function of the p-channel switch resistance (R_{PCH}) and the inductor resistance (R_{L}). The given values assume $R_{L} = 50 \text{m}\Omega$ for the REG1 inductor and $67 \text{m}\Omega$ for the REG2 inductor:

$$V_{DO} = I_{LOAD} (R_P + R_L)$$

Note 5: The maximum output current (IQUT(MAX)) is:

$$I_{OUT(MAX)} = \frac{I_{LIM} - \frac{V_{OUT}(1-D)}{2 \times f \times L}}{1 + (R_N + R_L) \frac{(1-D)}{2 \times f \times L}}$$

where:

 R_N = n-channel synchronous rectifier RDS (on)

Rp = p-channel power switch RDS (on)

R_L = external inductor ESR

I_{OUT(MAX)} = maximum output current provided by the PMIC

IOUT(TARGET) = maximum desired output current

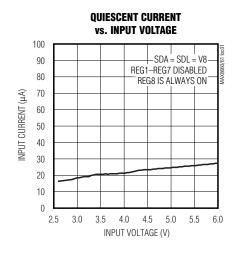
f = operating frequency minimum

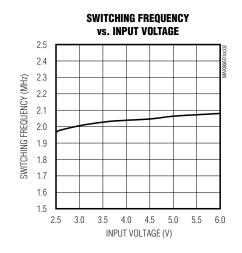
L = external inductor value

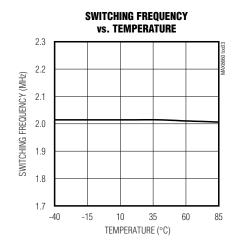
Note 6: Tested at 1.4V default output voltage for the MAX8660, MAX8660A, and MAX8661. Tested at 1.15V default output voltage for the MAX8660B.

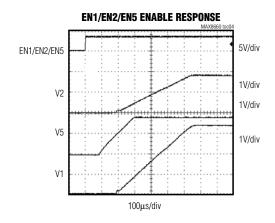
Note 7: All output voltages are possible in normal mode. In forced-PWM mode, the minimum output voltage is limited by 0.167 x V_{IN}. For example, with V_{IN} = 5.688V, the minimum output is 0.95V.

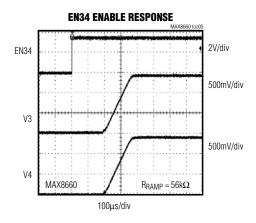
Typical Operating Characteristics



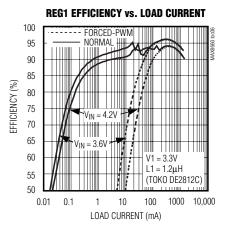


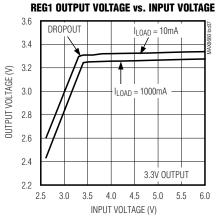


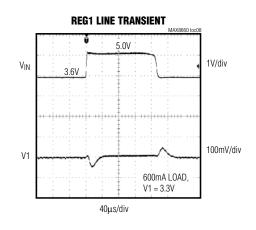


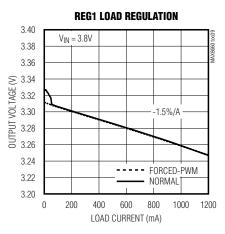


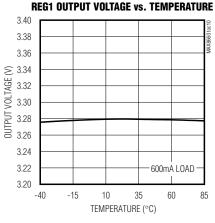
Typical Operating Characteristics (continued)

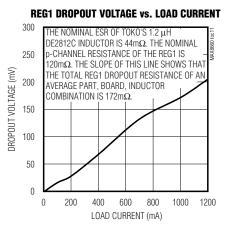


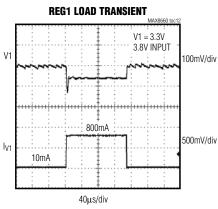


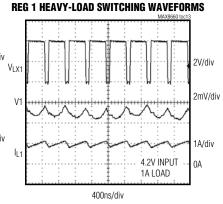


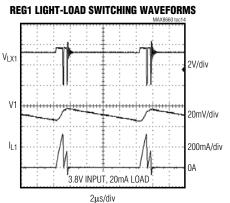




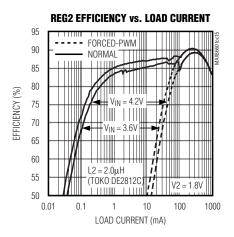


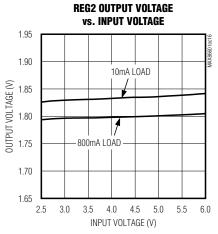


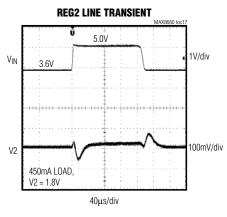


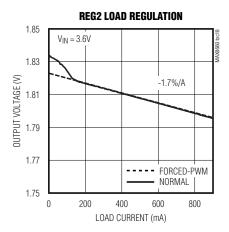


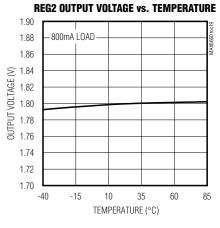
Typical Operating Characteristics (continued)

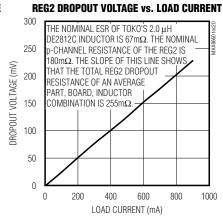


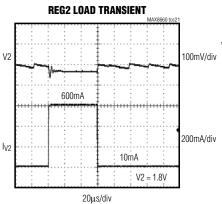


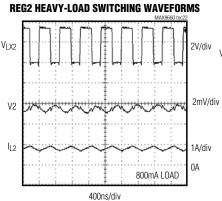


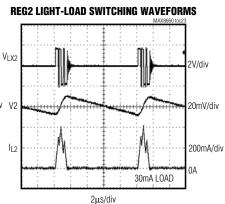




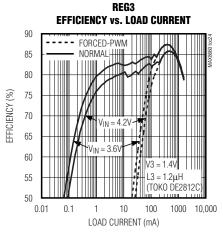


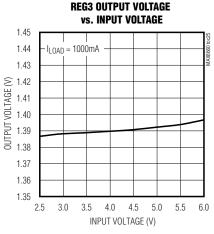


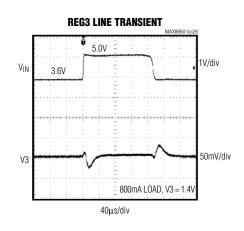


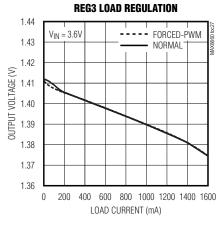


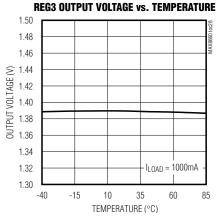
_Typical Operating Characteristics (continued)

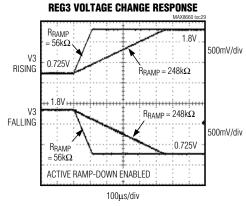


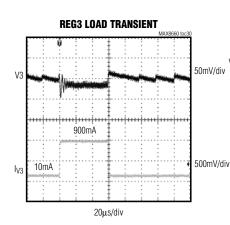


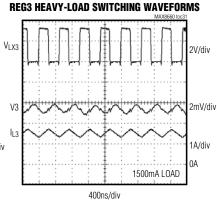


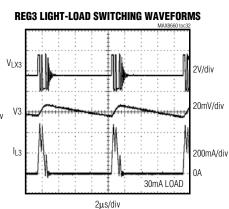




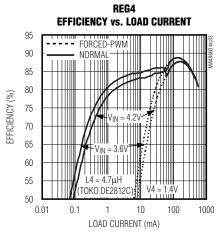


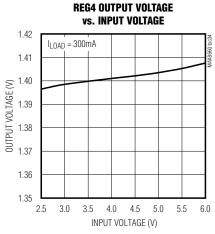


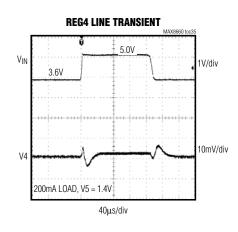


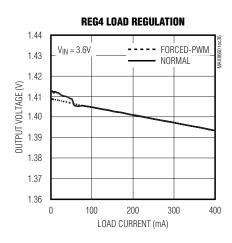


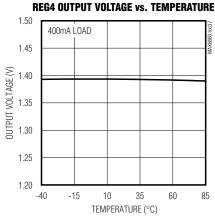
Typical Operating Characteristics (continued)

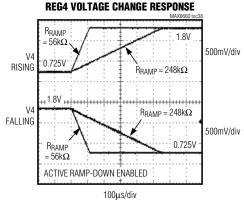


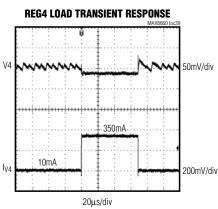


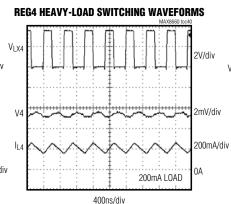


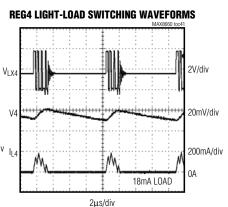






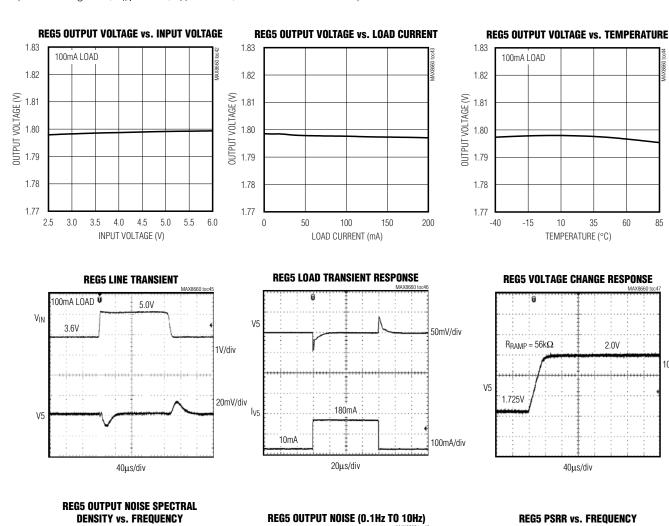


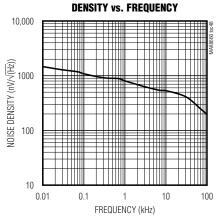


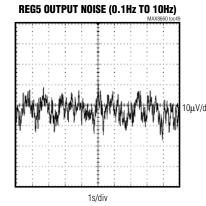


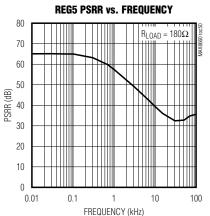
Typical Operating Characteristics (continued)

(Circuit of Figure 3, $V_{IN} = 3.6V$, $T_A = +25$ °C, unless otherwise noted.)





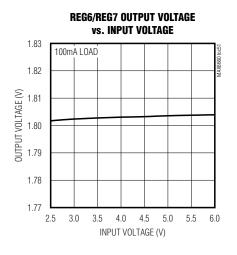


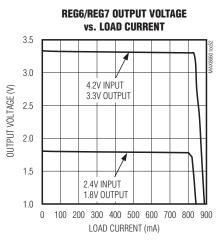


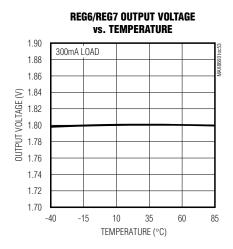
85

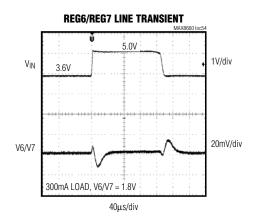
100mV/div

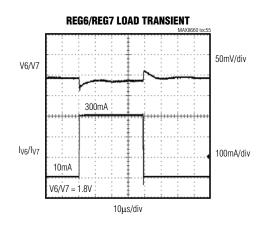
Typical Operating Characteristics (continued)

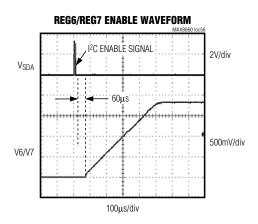


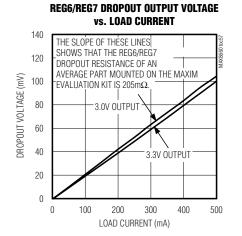




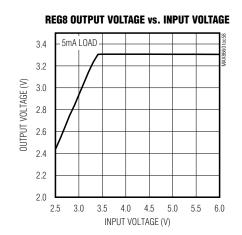


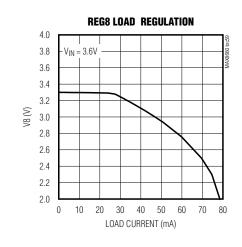


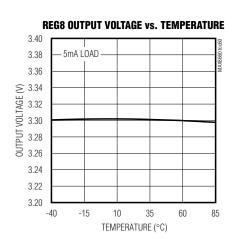


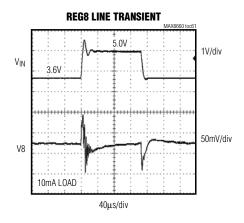


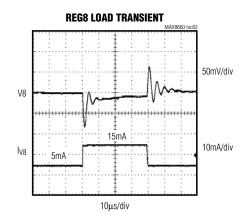
_Typical Operating Characteristics (continued)

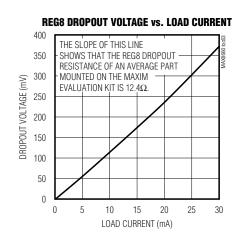












Pin Description

Р	IN		
MAX8660	MAX8861	NAME	FUNCTION
1	1	IN5	REG5 Power Input. Connect IN5 to IN to ensure V5 rises first to meet the Marvell PXA3xx processor's sequencing requirements. If adherence to this sequencing specification is not required, connect IN5 to V1, V2, or another supply between 2.35V and V _{IN} . See the <i>Linear Regulators (REG5–REG8)</i> section for more information.
_	2	V5	REG5 Linear-Regulator Output. V5 defaults to 1.8V and is adjustable from 1.7V to 2.0V through the serial interface. The input to the V5 regulator is IN5. Use V5 to power VCC_MVT , VCC_BG , VCC_OSC13M , and VCC_PLL on Marvell PXA3xx processors. V5 is internally pulled to AGND through $2k\Omega$ when REG5 is shut down.
3	3	PV4	REG4 Power Input. Connect a 4.7µF ceramic capacitor from PV4 to PG4. All PV pins and IN must be connected together externally.
4	4	LX4	REG4 Switching Node. Connect LX4 to the REG4 inductor. LX4 is high impedance when REG4 is shut down.
5	5	PG4	REG4 Power Ground. Connect PG1, PG2, PG3, PG4, and AGND together. Refer to the MAX8660 EV kit data sheet for more information.
6	6	SET2	REG2 Voltage Select Input. SET2 is a tri-level logic input. Connect SET2 to select the V2 output voltage as detailed in Table 4. The REG2 output voltage selected by SET2 is latched at the end of the REG2 soft-start period. Changes to SET2 after the startup period have no effect.
7	7	V6	REG6 Linear-Regulator Output. REG6 is activated and programmed through the serial interface to output from 1.8V to 3.3V in 0.1V steps. REG6 is off by default. V6 is internally pulled to AGND through 350Ω when REG6 is shut down. V6 optionally powers VCC_CARD1 on Marvell PXA3xx processors.
8	_	IN67	REG6 and REG7 Power Input. IN67 is typically connected to IN. IN67 can also be connected to any supply between 2.35V to $V_{\rm IN}$.
_	8	IN6	REG6 Power Input. IN6 is typically connected to IN. IN6 can also be connected to any supply between 2.35V to $V_{\rm IN}$.
9	_	V7	REG7 Linear-Regulator Output. REG7 is activated and programmed through the serial interface to output from 1.8V to 3.3V in 0.1V steps. REG7 is off by default. V7 is internally pulled to AGND through 350Ω when REG7 is shut down. V7 optionally powers VCC_CARD2 on Marvell PXA3xx processors.
_	9	N.C.	No Internal Connection
10	10	V2	REG2 Voltage Sense Input. Connect V2 directly to the REG2 output voltage. The output voltage of REG2 is selected by SET2. V2 is internally pulled to AGND through 650Ω when REG2 is shut down. V2 powers VCC_MEM on Marvell PXA3xx processors.
11	11	SCL	Serial-Clock Input. See the I ² C Interface section.
12	12	SDA	Serial-Data Input. See the I ² C Interface section.
13	13	ĪBO	Low-Battery Output. LBO is an open-drain output that pulls low when LBF is below its threshold. LBO typically connects to the <i>nBATT_FAULT</i> input of the applications processor to indicate that the battery has been removed or discharged.
14	14	PV2	REG2 Power Input. Connect a 4.7µF ceramic capacitor from PV2 to PG2. All PV pins and IN must be connected together externally.
15	15	LX2	REG2 Switching Node. Connect LX2 to the REG2 inductor. LX2 is high impedance when REG2 is shut down.

Pin Description (continued)

Р	IN		
MAX8660	MAX8661	NAME	FUNCTION
16	16	PG2	REG2 Power Ground. Connect PG1, PG2, PG3, PG4, and AGND together. Refer to the MAX8660 EV kit data sheet for more information.
17	17	IN8	REG8 Input Power Connection. IN8 must be connected to IN.
18	18	IN	Main Battery Input. This input provides power to the IC. Connect a 0.47µF ceramic capacitor from IN to AGND.
19	19	AGND	Analog Ground. Connect PG1, PG2, PG3, PG4, and AGND together. Refer to the MAX8660 EV kit data sheet for more information.
20	20	V8	REG8 Always-On 3.3V LDO Output. REG8 is the first regulator that powers up in the MAX8660/MAX8661. REG8 is supplied from IN and supplies up to 30mA. V8 is internally pulled to AGND through 1.5k Ω during IN undervoltage or overvoltage lockout. Connect V8 to VCC_BBATT on Marvell PXA3xx processors.
21	21	LBF	Low-Battery Detect Falling Input. The LBF threshold is 1.20V. Connect LBF to LBR for 50mV hysteresis. Use a three-resistor voltage-divider for larger hysteresis. LBF sets the falling voltage at which LBO goes low. See the <i>Low-Battery Detector</i> (LBO, LBF, LBR) section for more information.
22	22	LBR	Low-Battery Detect Rising Input. The LBR threshold is 1.25V. Connect LBF to LBR for 50mV hysteresis. Use a three-resistor voltage-divider for larger hysteresis. LBR sets the rising voltage at which LBO goes high. See the <i>Low-Battery Detector</i> (LBO, LBF, LBR) section for more information.
23	23	MR	Manual Reset Input. A low $\overline{\text{MR}}$ input causes $\overline{\text{RSO}}$ to go low and resets all serial programmed registers to their default values. See the <i>Reset Output (RSO)</i> and $\overline{\text{MR}}$ Input section for more information.
24	24	RAMP	Ramp-Rate Input. Connect a resistor from RAMP to AGND to set the regulator ramp rates. See the Ramp-Rate Control (RAMP) section for more information.
25	25	EN5	REG5 Enable Input. Drive EN5 high to turn on REG5. EN5 has hysteresis so an RC can be used to implement manual sequencing with respect to other inputs. EN5 is typically driven by the <i>SYS_EN</i> output of an Marvell PXA3xx processor.
26	26	PG3	REG3 Power Ground. Connect PG1, PG2, PG3, PG4, and AGND together. Refer to the MAX8660 EV kit data sheet for more information.
27	27	LX3	REG3 Switching Node. Connect LX3 to the REG3 inductor. LX3 is high impedance when REG3 is shut down.
28	28	PV3	REG3 Power Input. Connect a 4.7µF ceramic capacitor from PV3 to PG3. All PV pins and IN must be connected together externally.
29	29	RSO	Open-Drain Reset Output. RSO typically connects to the nRESET input on an applications processor. An output low from the MAX8660/MAX8661 RSO resets all serial programmed registers to their default values and causes the processor to enter its reset state. See the Reset Output (RSO) and MR Input section for more information.
30	30	V3	REG3 Voltage Sense Input. Connect V3 directly to the REG3 output voltage. The output voltage is adjustable from 0.725V to 1.8V through the serial interface. V3 is internally pulled to AGND through 550Ω when REG3 is shut down. V3 connects to VCC_APPS on Marvell PXA3xx processors.
31	31	EN34	REG3 and REG4 Active-High Hardware Enable Input. Drive EN34 high to enable both REG3 and REG4. Drive EN34 low to allow the serial interface to enable REG3 and REG4 independently. EN34 has hysteresis so an RC can be used to implement manual sequencing with respect to other inputs. EN34 is typically driven by the <i>PWR_EN</i> output of an Marvell PXA3xx processor. See the <i>REG3/REG4 Enable (EN34, EN3, EN4)</i> section for more information.

Pin Description (continued)

			Pili Description (continued)
Р	IN	NAME	FUNCTION
MAX8660	MAX8661		TONO HON
32	32	EN2	REG2 Enable Input. Drive EN2 high to turn on REG2. EN2 has hysteresis so that an RC can be used to implement manual sequencing with respect to other inputs. EN2 is typically driven by the SYS_EN output of an Marvell PXA3xx processor.
33	33	SRAD	Serial-Address Input. Connect SRAD to AGND for a 7-bit slave address of 0110 100 (0x68). Connect SRAD to IN to change the address to 0110 101 (0x6A). The eighth slave address bit is always zero since the MAX8660/MAX8661 are write-only. See the <i>Slave Address</i> section for more information.
34	_	PG1	REG1 Power Ground. Connect PG1, PG2, PG3, PG4, and AGND together. Refer to the MAX8660 EV kit data sheet for more information.
_	34	GND	Ground. Connect all GND pins to EP.
35	_	LX1	REG1 Switching Node. Connect LX1 to the REG1 inductor. LX1 is high impedance when REG1 is shutdown.
_	35	N.C.	No Internal Connection
36	_	PV1	REG1 Power Input. Connect a 4.7µF ceramic capacitor from PV1 to PG1. All PV pins and IN must be connected together externally.
_	36	PV	Power Input. All PV pins and IN must be connected together externally.
37	_	EN1	REG1 Enable Input. Drive EN1 high to turn on REG1. EN1 has hysteresis so that an RC can be used to implement manual sequencing with respect to other inputs. EN1 is typically driven by the <i>SYS_EN</i> output of an applications processor.
_	37	GND	Ground. Connect all GND pins to EP.
38	_	V1	REG1 Voltage Sense Input. Connect V1 directly to the REG1 output voltage. The output voltage of REG1 is selected by SET1. Connect V1 to VCC_IOx of the applications processor. V1 is internally pulled to AGND through 650Ω when REG1 is shut down.
	38	GND	Ground. Connect all GND pins to EP.
39	_	SET1	REG1 Voltage Select Input. SET1 is a tri-level logic input. Connect SET1 to select the V1 output voltage as detailed in Table 3. The REG1 output voltage selected by SET1 is latched at the end of the REG1 soft-start period. Changes to SET1 after the startup period have no effect.
	39	GND	Ground. Connect all GND pins to EP.
40	40	V4	REG4 Feedback Sense Input. Connect V4 directly to the REG4 output voltage. The REG4 output voltage is adjustable from 0.725V to 1.8V with the serial interface. V4 is internally pulled to AGND through 550Ω when REG4 is shut down. V4 powers VCC_SRAM on the applications processor.
_	_	EP	Exposed Pad. Connect the exposed pad to ground. Connecting the exposed pad to ground does not remove the requirement for proper ground connections to PG1, PG2, PG3, PG4, and AGND. The exposed pad is attached with epoxy to the substrate of the die, making it an excellent path to remove heat from the IC.

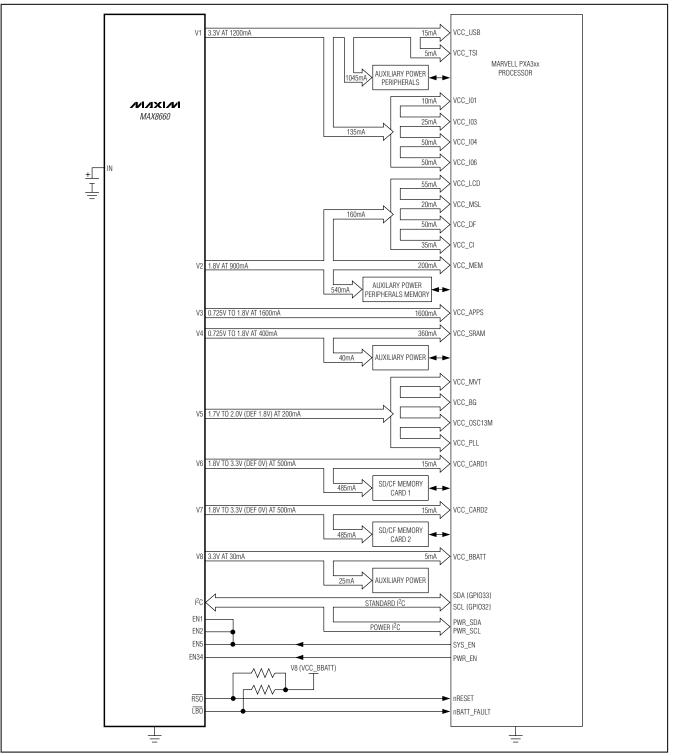


Figure 1. Example MAX8660 Connection to Marvell's PXA3xx Processor. This is one example only. Other connections are also supported.

22 ______/N/XI/M

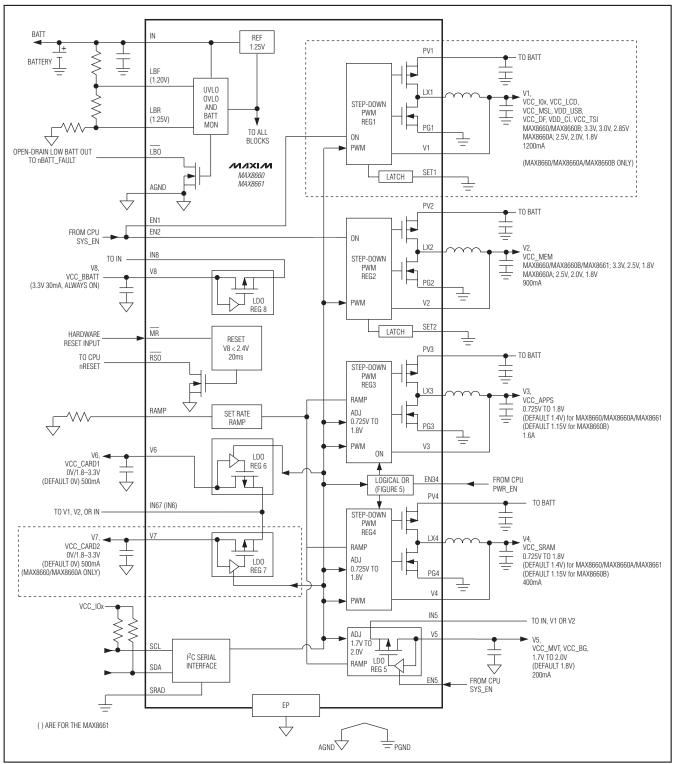


Figure 2. Functional Diagram

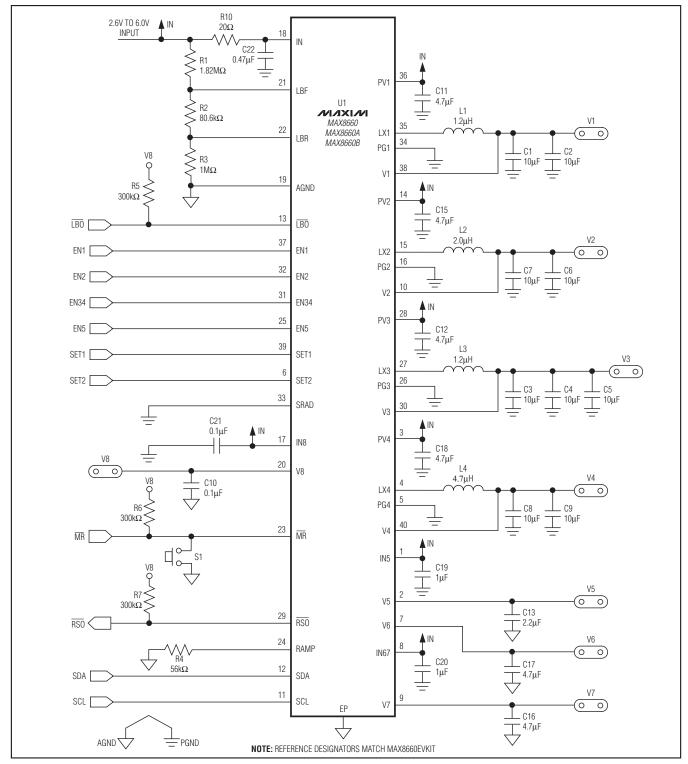


Figure 3. Typical Applications Circuit

Detailed Description

The MAX8660/MAX8661 PMICs are optimized for devices using the applications processors, including smart cellular phones, PDAs, Internet appliances, and other portable devices requiring substantial computing and multimedia capability and low power consumption. The MAX8660/MAX8661 comply with Marvell PXA3xx and PXA168 processor specifications.

As shown in Figure 2, the MAX8660 integrates eight high-performance, low-operating-current power supplies. REG1–REG4 are step-down DC-DC converters, and REG5–REG8 are linear regulators. Other functions include low-battery detection ($\overline{\text{LBO}}$), a reset output ($\overline{\text{RSO}}$), a manual reset input ($\overline{\text{MR}}$), and a 2-wire I²C serial interface. The MAX8661 functions the same as the MAX8660, but does not have the REG1 step-down regulator and the REG7 linear regulator.

The operating input voltage range is from 2.6V to 6.0V, allowing use with a 1-cell Li+ battery, 3-cell NiMH, or a 5V input. Input protection is provided with undervoltage and overvoltage lockouts. Overvoltage lockout protects the device against inputs up to 7.5V.

Maxim vs. Marvell PXA3xx Terminology

The MAX8660/MAX8661 are compatible with Marvell's PXA3xx processor. Figure 1 shows one of many possible connections between the PXA3xx processor and the MAX8660/MAX8661. To facilitate system development with PXA3xx processors, this document uses both Maxim and Marvell terminology. Marvell terminology appears in parentheses and italics. For example, this document refers to "V8 (VCC_BBATT)" because the MAX8660 V8 output powers the Marvell VCC_BBATT power domain. Tables 1 and 2 outline Maxim and Marvell terminology.

Table 1. Maxim and Marvell PXA3xx Power Domain Terminology

POWER DOMAIN	POWER DOMAIN ACCEPTABLE VOLTAGE	COMPATIBLE MAXIM POWER DOMAIN	DESCRIPTION
VCC_IO1 VCC_IO3 VCC_IO4 VCC_IO6	1.8V ±10% or 3.0V ±10% or 3.3V ±10%	V1 or V2	Peripheral I/O supply for UARTs, standard I ² C, power I ² C, audio interface, SSPs, PWMs, etc. (VCC_IO1, VCC_IO3, VCC_IO4, VCC_IO6)
VCC_LCD VCC_MSL VCC_CI VCC_DF	1.8V ±10% or 3.0V ±10%	V1 or V2	 LCD interface logic (VCC_LCD) Fast serial interface (VCC_MSL) Camera flash interface (VCC_CI) Data flash interface (VCC_DF)
VCC_MEM	1.8V ±100mV	V2	I/O supply for high-speed memory
VCC_APPS	0.95V to 1.41V ±5%	V3	Main processor core
VCC_SRAM	1.08V to 1.41V ±100mV	V4	Internal SRAM memory
VCC_MVT VCC_BG VCC_OSC13M VCC_PLL	1.8V ±100mV	V5	 Internal logic and I/O blocks (VCC_MVT) Bandgap reference (VCC_BG) 13MHz oscillator (VCC_OSC13M) Phase-locked loop (PLL) and oscillator (VCC_PLL)
VCC_CARD1	1.8V \pm 10% or 3.0V \pm 10% or 3.3V \pm 10%	V6	Removable storage and USIM card supply
VCC_CARD2	1.8V ±10% or 3.0V ±10% or 3.3V ±10%	V7	Removable storage and USIM card supply
VCC_BBATT	3.0V ±1V	V8	Regulated battery voltage
VCC_USB	3.3V ±300mV	V1 or V2 (if programmed to 3.3V)	Universal serial bus (VCC_USB)
VCC_TSI	3.3V ±300mV	V1 or V2 (if programmed to 3.3V)	Touch-screen interface (VCC_TSI)

Table 2. Maxim and Marvell PXA3xx Digital Signal Terminology

MAXIM	MARVELL	DESCRIPTION
EN34	PWR_EN	Active-High Enable Signal for Processor Core Power. The applications processor drives this <i>PWR_EN</i> signal high to exit sleep mode. The processor's PWR_EN logic is powered by the MAX8660/MAX8661 "always on" V8 (<i>VCC_BBATT</i>) regulator during sleep mode.
EN1, EN2, EN5	SYS_EN	Active-High Enable Signal for Peripheral Power Supplies. The applications processor drives this SYS_EN signal high to enter run mode.
RSO	nRESET	Active-Low Reset. The MAX8660/MAX8661 drive this signal low to reset the processor. When RSO goes low, the MAX8660/MAX8661 l²C registers are reset to their default values.
LBO	nBATT_FAULT	Active-Low Battery Fault. The MAX8660/MAX8661 drive this signal low to signal the processor that the battery has been removed or discharged.
SDA	GPIO33 PWR_SDA	l ² C Serial-Data Input/Output. The MAX8660/MAX8861 SDA generally connects to both the Marvell PXA3xx processor's standard l ² C data line (<i>GPIO33</i>) and its dedicated power l ² C data line. This connection operates as an l ² C multimaster system with the MAX8660/MAX8661 accepting commands from both the standard l ² C and the power l ² C.
SCL	GPIO32 PWR_SCL	I ² C Serial Clock. The MAX8660/MAX8661 SCL generally connects to both the Marvell PXA3xx processor's standard I ² C clock line (<i>GPIO32</i>) and its dedicated power I ² C clock line. This connection operates as an I ² C multimaster system with the MAX8660/MAX8661 accepting commands from both the standard I ² C and the power I ² C.

Step-Down DC-DC Converters (REG1-REG4)

REG1 (VCC_IO) Step-Down DC-DC Converter (MAX8660 Only)

REG1 is a high-efficiency (REG1 + REG8 IQ = 40μ A) 2MHz current-mode step-down converter that outputs up to 1200mA with efficiency up to 96% (see *the Typical Operating Characteristics*). The output voltage (V1) is selected with the SET1 input as shown in Table 3. The REG1 output voltage selection is latched at the end of the REG1 soft-start period. Changes in SET1 after the startup period have no effect.

EN1 is a dedicated enable input for REG1. Drive EN1 high to enable REG1 or drive EN1 low to disable REG1. EN1 has hysteresis so that an RC may be used to implement manual sequencing with respect to other inputs. In systems based on Marvell PXA3xx processors, EN1, EN2, and EN5 are typically connected to *SYS_EN* (Table 2).

The REG1 step-down regulator operates in either normal or forced-PWM mode. See the *REG1-REG4 Step-Down DC-DC Converter Operating Modes* section for more information.

REG1 has an on-chip synchronous rectifier. See the *REG1-REG4 Synchronous Rectification* section for more information.

The REG1 regulator allows 100% duty-cycle operation. See the *REG1/REG2 100% Duty-Cycle Operation* (*Dropout*) section for more information.

Table 3. SET1 Logic

SET1*	MAX8660/ MAX8660B: V1 (V)	MAX8660A: V1 (V)
IN	3.3	2.5
UNCONNECTED	3.0	2.0
GROUND	2.85	1.8

^{*}SET1 is latched after REG1 startup.

Table 4. SET2 Logic

SET2*	MAX8660/MAX8660B/ MAX8661: V2 (V)	MAX8660A: V2 (V)
IN	3.3	2.5
UNCONNECTED	2.5	2.0
GROUND	1.8	1.8

^{*}SET2 is latched after REG2 startup.

REG2 (VCC_IO, VCC_MEM) Step-Down DC-DC Converters

REG2 is a high-efficiency (REG2 + REG8 IQ = 40μ A) 2MHz current-mode step-down DC-DC converter that outputs up to 900mA with efficiency up to 96%. The output voltage is selected with the SET2 input as shown in Table 4. The REG2 output voltage selection is latched at the end of the REG2 soft-start period. Changes in SET2 after the startup period have no effect.

____ /VI/XI/VI

EN2 is a dedicated enable input for REG2. Drive EN2 high to enable REG2 or drive EN2 low to disable REG2. EN2 has hysteresis so that an RC may be used to implement manual sequencing with respect to other inputs. In systems based on Marvell PXA3xx, EN1, EN2, and EN5 are typically connected to *SYS_EN* (Table 2).

The REG2 step-down regulator operates in either normal or forced-PWM mode. See the *REG1-REG4 Step-Down DC-DC Converter Operating Modes* section for more information.

The REG2 regulator has an on-chip synchronous rectifier. See the *REG1–REG4 Synchronous Rectification* section for more information.

The REG2 regulator allows 100% duty-cycle operation. See the *REG1/REG2 100% Duty-Cycle Operation* (*Dropout*) section for more information.

REG3 (VCC_APPS) Step-Down DC-DC Converters

REG3 is a high-efficiency (REG3 + REG8 IQ = 45μ A) 2MHz current-mode step-down converter that has an I²C-adjustable output voltage from 0.725V to 1.800V in 25mV increments with efficiency up to 92%. The default REG3 output voltage is 1.4V for the MAX8660/MAX8660A/MAX8661, and 1.15V for the MAX8660B (contact factory for other default voltages). REG3 delivers up to 1.6A. See the *I²C Interface* section for details on how to adjust the output voltage.

REG3 has an I²C enable bit (EN3) and a shared hardware enable pin (EN34). See the *REG3/REG4 Enable* (EN34, EN3, EN4) section for more information.

The REG3 step-down regulator operates in either normal or forced-PWM mode. See the *REG1–REG4 Step-Down DC-DC Converter Operating Modes* section for more information.

The REG3 regulator has an on-chip synchronous rectifier. See the *REG1–REG4 Synchronous Rectification* section for more information.

REG4 (VCC_SRAM) Step-Down DC-DC Converters

REG4 is a high-efficiency (REG4 + REG8 IQ = 45μ A) 2MHz current-mode step-down converter that has an I²C-adjustable output voltage from 0.725V to 1.800V in 25mV increments with efficiency up to 92%. The default REG4 output voltage is 1.4V for the MAX8660/MAX8660A/MAX8661, and 1.15V for the MAX8660B (contact factory for other default voltages). REG4 delivers up to 400mA. See the I²C Interface section for details on how to adjust the output voltage.

REG4 has an I²C enable bit (EN4) and a shared hardware enable pin (EN34). See the *REG3/REG4 Enable* (EN34, EN3, EN4) section for more information.

The REG4 step-down regulator operates in either normal or forced-PWM mode. See the *REG1-REG4 Step-Down DC-DC Converter Operating Modes* section for more information.

The REG4 regulator has an on-chip synchronous rectifier. See the *REG1–REG4 Synchronous Rectification* section for more information.

REG1-REG4 Step-Down DC-DC Converter Operating Modes

REG1-REG4 independently operate in one of two modes: normal or forced PWM. At power-up or after a reset, REG1-REG4 default to normal operation. Activate forced-PWM mode by setting bits in the FPWM register (Table 9) with the I²C interface. The FPWM bits can be changed at any time.

In forced-PWM mode, a converter operates with a constant 2MHz switching frequency regardless of output load. The MAX8660/MAX8661 regulate the output voltage by modulating the switching duty cycle. Forced-PWM mode is ideal for low-noise systems because output voltage ripple is small (< 10mVp-p) and switching harmonics occur at multiples of the constant-switching frequency and are easily filtered. However, light-load power consumption in forced-PWM mode is higher than that of normal mode (Table 7).

Normal operation offers improved efficiency at light loads by switching only as necessary to supply the load. With moderate to heavy loading, the regulator switches at a fixed 2MHz switching frequency as it does in forced-PWM mode. This transition to fixed-frequency switching occurs at the load current specified in the following equation:

$$I_{OUT} \cong \frac{V_{IN} - V_{OUT}}{2 \times L} \times \frac{V_{OUT}}{V_{IN} \times f_{SW}}$$

REG1-REG4 Synchronous Rectification

Internal n-channel synchronous rectifiers eliminate the need for external Schottky diodes and improve efficiency. The synchronous rectifier turns on during the second half of each switching cycle (off-time). During this time, the voltage across the inductor is reversed, and the inductor current ramps down. In PWM mode, the synchronous rectifier turns off at the end of the switching cycle. In normal mode, the synchronous rectifier turns off when the inductor current falls below 25mA or at the end of the switching cycle, whichever occurs first.

REG1/REG2 100% Duty-Cycle Operation (Dropout)

The REG1 and REG2 step-down DC-DC converters operate with 100% duty cycle when the supply voltage approaches the output voltage. This allows these

converters to maintain regulation until the input voltage falls below the desired output voltage plus the dropout voltage specification of the converter. During 100% duty-cycle operation, the high-side p-channel MOSFET turns on constantly, connecting the input to the output through the inductor. The dropout voltage (VDO) is calculated as follows:

 $V_{DO} = I_{LOAD} (R_P + R_L)$

where:

 R_P = p-channel power switch $R_{DS(ON)}$ R_I = external inductor ESR

The REG1 dropout voltage is 200mV with a 1200mA load (with inductor resistance = 50m Ω). The REG2 dropout voltage is 225mV with a 900mA load (with inductor resistance = 67m Ω).

Linear Regulators (REG5-REG8) REG5 (VCC_MVT, VCC_BG, VCC_OSC13M, VCC_PLL)

REG5 is a linear regulator with an I^2C -adjustable output voltage from 1.700V to 2.000V in 25mV increments (REG5 + REG8 IQ = 55 μ A). The default REG5 voltage is 1.8V. REG5 delivers up to 200mA. See the I^2C Interface section for details on how to adjust the output voltage.

The power input for the REG5 linear regulator is IN5. The IN5 input voltage range extends down to 2.35V. Note that in the Marvell PXA3xx specification, *VCC_MVT* is enabled by *SYS_EN* (along with V1 and V2), but must not rise after V1 (*VCC_IO*) or V2 (*VCC_MEM*). This requirement dictates that IN5 be connected to IN and not V1 or V2.

EN5 is a dedicated enable input for REG5. Drive EN5 high to enable REG5. Drive EN5 low to disable REG5. EN5 has hysteresis so that an RC may be used to implement manual sequencing with respect to other inputs. In systems with Marvell PXA3xx processors, EN1, EN2, and EN5 are typically connected to *SYS_EN* (Table 2).

REG6/REG7 (VCC_CARD1, VCC_CARD2)

The REG6/REG7 linear regulators supply up to 500mA each (REG6 or REG 7 + REG8 IQ = 85μ A). The output voltages, V6 and V7, are programmable through the serial interface from 1.8V to 3.3V in 0.1V steps (Table 13). See the *I*²*C Interface* section for details on changing the V6 or V7 voltage. On the MAX8660, the combined power input for the REG6 and REG7 linear regulators is IN67. On the MAX8661, IN6 is the power input for REG6 (REG7 is not available on the MAX8661).

REG6 and REG7 are disabled by default and must be enabled using the I^2C serial interface. REG6 and REG7 have independent enable bits in the OVER2 register: EN6 and EN7 (Table 9). To enable the regulators, set the corresponding enable bit.

REG8 (VCC BBATT) Always-On Regulator

The output of REG8 (V8) is always active when the input voltage (VIN) is above the undervoltage-lockout threshold of 2.55V (max) and below the overvoltage-lockout threshold of 6.0V (min). The REG8 linear regulator is supplied from IN and its output regulates to 3.3V and supplies up to 30mA. The internal REG8 pass element is 12Ω in dropout, providing a 180mV dropout voltage with a 15mA output current. Connect V8 to VCC_BBATT for applications that use Marvell PXA3xx processors. The RSO output goes low if V8 is less than 2.2V (falling typ).

Ramp-Rate Control (RAMP)

REG1 and REG2 have a fixed soft-start ramp that eliminates input current spikes when they are enabled; 200µs after being enabled, REG1 and REG2 linearly ramp from 0V to the set output voltage in 450µs. When these regulators are disabled, the output voltage decays at a rate determined by the output capacitance, internal 650Ω discharge resistance, and the external load.

The REG3 and REG4 output voltage have a variable linear ramp rate that is set by a resistor connected from RAMP to AGND (R_{RAMP}). This resistor controls the output-voltage ramp rate during soft-start and a positive voltage change (i.e., 1.0V to 1.4V). The negative voltage change (i.e., 1.4V to 1.0V) is controlled in forced-PWM mode, and when the ARD bit is set in normal mode (Table 9). Figure 4 shows the relationship

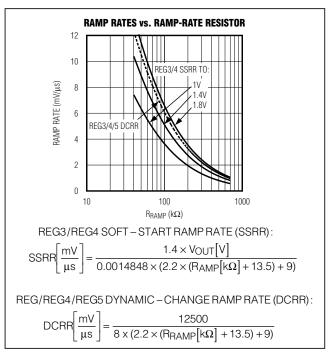


Figure 4. Soft-Start and Voltage-Change Ramp Rates

between RRAMP and the output-voltage ramp rates. A $56k\Omega$ RRAMP satisfies the typical requirements of Marvell PXA3xx processors; 200µs after being enabled, REG3 and REG4 linearly ramp from 0V to the set output voltage at the rate set by RRAMP. When REG3 and REG4 are disabled, the output voltage decays at a rate determined by the output capacitance, internal 550Ω discharge resistance, and the external load.

Active ramp-down functionality is inherent in forced-PWM operation. In normal-mode operation, active ramp down is enabled by setting ARD3 and ARD4 (Table 9). With "active ramp-down" enabled, the regulator output voltage ramps down at the rate set by RRAMP. With small loads, the regulator must sink current from the output capacitor to actively ramp down the output voltage. In normal mode, with "active ramp-down" disabled, the regulator output voltage ramps down at the rate determined by the output capacitance and the external load; small loads result in an output-voltage decay that is slower than that specified by RRAMP, large loads (> COUT x RAMPRATE) result in an output-voltage decay that is no faster than that specified by RRAMP.

80µs after being enabled, REG5 linearly ramps from 0V to the set output voltage in 225µs. The ramp rate during a positive voltage change (i.e., 1.8V to 1.9V) is set with RRAMP. During a negative voltage change (i.e., 1.9V to 1.8V), the REG5 output voltage decays at a rate determined by the output capacitance and the external load; however, ramp-down is no faster than the rate specified by RRAMP. When REG5 is disabled, the output voltage decays at a rate determined by the output capacitance, internal $2k\Omega$ discharge resistance, and the external load.

60µs after being enabled by I²C, REG6 and REG7 linearly ramp from 0V to the set output voltage in 450µs. REG6 and REG7 do not have positive voltage-change

(i.e., 1.8V to 2.5V) ramp-rate control. During a positive voltage change, the output-voltage dV/dt is as fast as possible. To avoid this fast output dV/dt, disable REG6 or REG7 before changing the output. With this method, the soft-start ramp rate limits the output dV/dt, and therefore, the input current is controlled. During a negative voltage change (i.e., 2.5V to 1.8V), the REG6 or REG7 output voltage decays at a rate determined by the output capacitance and the external load. When REG6 or REG7 is disabled, the output voltage decays at a rate determined by the output capacitance, internal 350Ω discharge resistance, and the external load.

Power Sequencing

Enable Signals (EN , PWR EN, SYS EN, I²C)

As shown in Table 5, the MAX8660/MAX8661 feature numerous enable signals for flexibility in many applications. In a typical application with the Marvell PXA3xx processor, many of these enable signals are connected together. EN1, EN2, and EN5 typically connect to the SYS EN output. With this connection, REG5 is the first supply to rise (if IN5 is connected to IN). EN34 typically connects to Marvell's PWR_EN output. Alternatively, REG3 and REG4 can be activated by the I2C interface (see the REG3/REG4 Enable (EN34, EN3, EN4) section for more information). REG6 and REG7 are activated by the serial interface. REG8 has no enable input and always remains on as long the MAX8660/MAX8661 are powered between the UVLO and OVLO range. All regulators are forced off during UVLO and OVLO. See the Undervoltage and Overvoltage Lockout section for more information.

Note: The logic that controls the Marvell PXA3xx processor *SYS_EN* and *PWR_EN* signals is powered from the *VCC_BBATT* power domain.

Table 5. Enable Signals

POWER DOMAIN	MAXIM ENA	BLE SIGNAL	APPLICATIONS PROCESSOF	
POWER DOMAIN	HARDWARE	SOFTWARE	ENABLE SIGNAL	
V1 (VCC_IO) (MAX8660/MAX8660A only)	EN1	_		
V2 (<i>VCC_MEM</i>)	EN2	_	SYS_EN	
V5 (VCC_MVT)	EN5	_		
V3 (<i>VCC_APPS</i>)	EN34	EN3 (OVER1)	PWR_EN &	
V4 (VCC_SRAM)	EN34	EN4 (OVER1)	PWR_I ² C	
V6 (VCC_CARD1)	_	EN6 (OVER2)	Standard I ² C	
V7 (VCC_CARD2) (MAX8660/MAX8660A only)	_	EN7 (OVER2)	Standard I-C	
V8 (VCC_BBATT)	Alwa	ys on	_	

REG3/REG4 Enable (EN34, EN3, EN4)

REG3 and REG4 have independent I²C enable bits (EN3, EN4) and a shared hardware-enable input (EN34). As shown in Figure 5, the EN34 hardware-enable input is logically ORed with the I²C enable bits. Table 6 is the truth table for the V3/V4 enable logic. Note that to achieve a pure I²C enable/disable, connect EN34 to ground. Similarly, to achieve a pure hardware enable/disable, leave the I²C enable bits at their default value (EN3 = EN4 = 0 = off); V3 and V4 cannot be independently enabled/disabled using only hardware.

Note: A low \overline{MR} drives \overline{RSO} low and returns the I²C registers to their default values: EN3 = 0 and EN4 = 0.

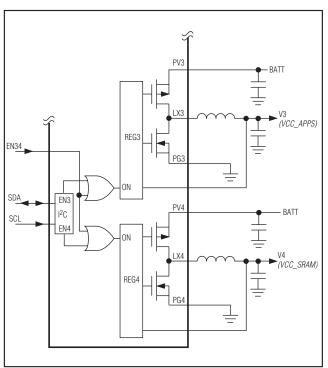


Figure 5. V3/V4 Enable Logic

Table 6. Truth Table for V3/V4 Enable Logic

HARDWARE INPUT	I2C I	V3	V4	
EN34	EN3	EN4	V3	V4
0	0 (default)	0 (default)	OFF	OFF
0	0	1	OFF	ON
0	1	0	ON	OFF
X	1	1	ON	ON
1	Х	Х	ON	ON

X = Don't care.

Power Modes

The MAX8660/MAX8661 provide numerous enable signals (Table 5) and support any combination for enabling and disabling their supplies with these signals. Table 7 shows several power modes defined for PXA3xx processors along with their corresponding MAX8660/MAX8661 quiescent operating currents.

Power-Up and Power-Down Timing

Figure 6 shows the power-up sequence for the Marvell PXA3xx family of processors. In general, the supplies should power up in the following order:

- 1) POWER-UP: V8 \rightarrow V5 \rightarrow V1 and V2 \rightarrow V3 and V4
- REG6 and REG7 typically power external card slots and can be powered up and down based on application requirements.

Note that the Marvell PXA3xx processor controls EN1/EN2/EN5 with the same *SYS_EN* signal, yet Marvell's timing diagrams show that V5 is supposed to power up before V1 and V2. Because of the PXA3xx family's timing parameters, most systems connect EN1/EN2/EN5 together and drive them with *SYS_EN*. When powering up, this connection ensures that V5 powers up before V1 and V2 (only when V5 is powered from IN).

Marvell PXA3xx Power Configuration Register (PCFR)

The MAX8660/MAX8661 comply with the Marvell PXA3xx power I²C register specifications. This allows the PMIC to be used along with the processor with little-to-no software development. As shown in Table 9, there are many I²C registers, but since the processor automatically updates the PMIC through its power I²C interface, only the REG6 and REG7 enable bits need be programmed to fully utilize the PMIC.

The Marvell PXA3xx processor contains a power management unit general configuration register (PCFR). The default values of this register are compliant with the MAX8660/MAX8661. However, wake-up performance can be optimized using this register:

- The PCFR register contains timers for the SYS_DEL and PWR_DEL timing parameters as shown in Figure 6. Each timer defaults to 125ms. When using the MAX8660/MAX8661, these timers may be shortened to 2ms to speed up the overall system wake-up delay.
- Enabling the "shorten wake-up delay" function (SWDD bit) bypasses the SYS_DEL and PWR_DEL timers and uses voltage detectors on the Marvell PXA3xx processor to optimize the overall system wake-up delay.

Table 7. Power Modes and Corresponding Quiescent Operating Currents

POWER	POWER DOMAIN	DIGITAL CONTROL	MAX8660 QUIESCENT OPERATING CURRENT (FIGURE 3)			
MODE	STATE	STATE	NORMAL OPERATING MODE	FORCED-PWM MODE		
ALL ON	V1, V2, V3, V4, V5, V6, V7, and V8 are on	EN1/EN2/EN5 (SYS_EN) and EN34 (PWR_EN) are asserted. V6, V7 are enabled by I ² C	250μΑ	23mA		
RUN, IDLE, and	V1, V2, V3, V4, V5, and V8 are on	EN1/EN2/EN5 (SYS_EN) and EN34 (PWR_EN) are asserted	140μΑ	22.9mA		
STANDBY	V6 and V7 are off	V6 and V7 are disabled by I ² C (default)				
	V1, V2, V5, and V8 are on	EN1/EN2/EN5 (SYS_EN) are asserted				
SLEEP	V3, V4, V6, and V7 are off	EN34 (<i>PWR_EN</i>) is deasserted; V6 and V7 are disabled by I ² C (default)	90μΑ	10mA		
DEEP SLEEP	All supplies off except V8	EN1/EN2/EN5 (SYS_EN) and EN34 (PWR_EN) are deasserted; V6, V7 are disabled by I ² C	20μΑ			

Note: Forced-PWM currents are measured on the MAX8660 EV kit. Currents vary with step-down inductor and output capacitor tolerance.

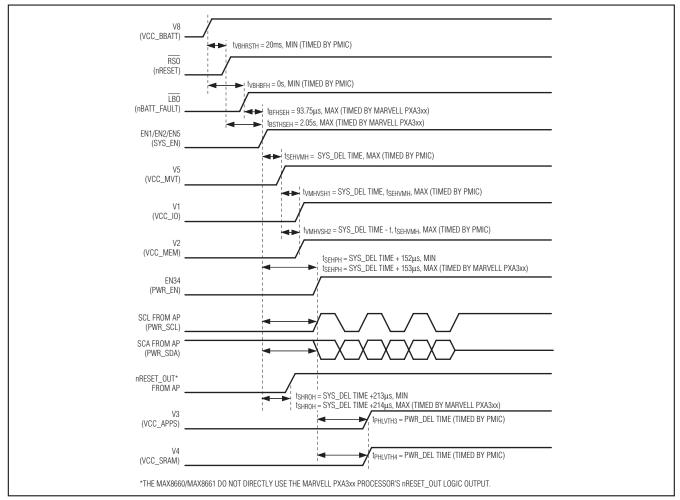


Figure 6. Power-Up Timing

Voltage Monitors, Reset, and Undervoltage-Lockout Functions

Undervoltage and Overvoltage Lockout

When the V_{IN} is below V_{UVLO} (typically 2.35V), the MAX8660/MAX8661 enter its undervoltage-lockout mode (UVLO). UVLO forces the device to a dormant state. In UVLO, the input current is very low (1.5 μ A) and all regulators are off. RSO and LBO are forced low when the input voltage is between 1V (typ) and V_{UVLO}. The I²C does not function in UVLO, and the I²C register contents are reset in UVLO.

When the input voltage is above V_{OVLO} (typically 6.35V) the MAX8660/MAX8661 enter overvoltage-lockout mode (OVLO). OVLO mode protects the MAX8660/MAX8661 from high-voltage stress. In OVLO, the input current is 25µA and all regulators are off. $\overline{\text{RSO}}$ is held low, the I²C does not function, and register contents are reset in OVLO. $\overline{\text{LBO}}$ continues to function in OVLO; however, since $\overline{\text{LBO}}$ is typically pulled up to V8 (VCC_BBATT), $\overline{\text{LBO}}$ appears to go low in OVLO because V8 is disabled. Alternatively, $\overline{\text{LBO}}$ may be pulled up to IN.

Reset Output (RSO) and MR Input

RSO is an open-drain reset output. As shown in Figure 1, RSO typically connects to the *nRESET* input of the applications processor and is pulled up to V8 (*VCC_BBATT*). A low on *nRESET* causes the processor to enter its reset state.

RSO is forced low when one or more of the following conditions occur:

- \overline{MR} is low.
- V8 is below VRSOTH (2.2V falling typ).
- V_{IN} is below V_{UVLO} (2.35V typ).
- V_{IN} is above V_{OVLO} (6.35V typ).

RSO is high impedance when all of the following conditions are satisfied:

- MR is high.
- V8 is above VRSOTH (2.35V rising typ).
- VUVLO < VIN < VOVLO.
- The $\overline{\rm RSO}$ deassert delay (tybhrsth = 24ms typ) has expired.

When RSO goes low, the MAX8660/MAX8661 I²C registers are reset to their default values.

If the $\overline{\text{MR}}$ feature is not required, connect $\overline{\text{MR}}$ high. If the $\overline{\text{RSO}}$ feature is not required, connect $\overline{\text{RSO}}$ low.

Low-Battery Detector (LBO, LBF, LBR)

LBO is an open-drain output that typically connects to the *nBATT_FAULT* input of the applications processor to indicate that the battery has been removed or discharged (Figure 1). LBO is typically pulled up to V8 (*VCC_BBATT*).

LBR and LBF monitor the input voltage (usually a battery) and trigger the LBO output (Figure 7). The truth table in Figure 7 shows that LBO is high impedance when the voltage from LBR to AGND (VLBR) exceeds the low-battery rising threshold (VLBRTH = 1.25V (typ). LBO is low when the voltage from LBF to AGND (VLBF) falls below the low-battery falling threshold (VLBFTH = 1.20V typ). On power-up, the LBR threshold must be exceeded before LBO deasserts.

Connecting LBF to LBR and to a two-resistor voltage-divider sets a 50mV hysteresis referred to LBF (hysteresis at the battery voltage is scaled up by the resistor value), connecting LBF and LBR separately to a three-resistor voltage-divider (Figure 7) allows the falling threshold and rising threshold to be set separately (achieving larger hysteresis). The Figure 7 resistor values are selected as a function of the desired falling (V_{LBOF}) and rising (V_{LBOR}) thresholds as follows:

First, select R3 in the $100k\Omega$ to $1M\Omega$ range:

R1 = R3 ×
$$\frac{V_{LBOR}}{V_{LBRTH}}$$
 × $\left(1 - \frac{V_{LBFTH}}{V_{LBOF}}\right)$
R2 = R3 × $\left(\frac{V_{LBFTH} \times V_{LBOR}}{V_{LBRTH} \times V_{LBOF}} - 1\right)$

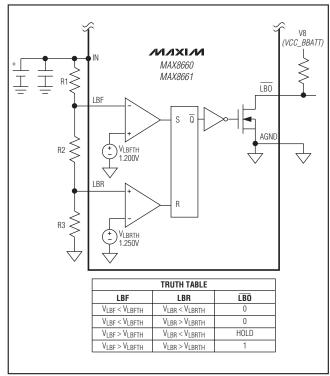


Figure 7. Low-Battery Detector Functional Diagram

where V_{LBOR} is the rising voltage at the top of R1 (typically V_{IN}) when \overline{LBO} goes high, and V_{LBOF} is the falling voltage at the top of R1 when \overline{LBO} goes low.

For example, to set V_{LBOR} to 3.6V and V_{LBOF} to 3.2V, choose R3 to be 1M Ω . Then, R1 = 1.8M Ω and R2 = 80k Ω .

If the low-battery-detector feature is not required, connect $\overline{\text{LBO}}$ to ground and connect LBF and LBR to IN.

Internal Off-Discharge Resistors

Each regulator on the MAX8660/MAX8661 has an internal resistor that discharges the output capacitor when the regulator is off (Table 8). The internal discharge resistors pull their respective output to ground when the regulator is off, ensuring that load circuitry always powers down completely. The internal off-discharge resistors are active when a regulator is disabled, when the device is in OVLO, and when the device is in UVLO with V_{IN} greater than 1.0V. With V_{IN} less than 1.0V, the internal off-discharge resistors may not activate.

Thermal-Overload Protection

Thermal-overload protection limits total power dissipation in the MAX8660/MAX8661. When internal thermal sensors detect a die temperature in excess of +160°C, the corresponding regulator(s) are shut down, allowing the IC to cool. The regulators turn on again after the junction cools by 15°C, resulting in a pulsed output during continuous thermal-overload conditions.

A thermal overload on any of REG1 through REG5 only shuts down the overloaded regulator. An overload on REG6 or REG7 shuts down both regulators together. During thermal overload, REG8 is not turned off, and the I²C interface and voltage monitors remain active.

Table 8. Internal Off-Discharge Resistor

REGULATOR	INTERNAL OFF-DISCHARGE RESISTOR VALUE
REG1	650Ω ±30%
REG2	650Ω ±30%
REG3	550Ω ±30%
REG4	550Ω ±30%
REG5	2kΩ ±30%
REG6	350Ω ±30%
REG7	350Ω ±30%
REG8	1.5kΩ ±30%

I²C Interface

An I²C-compatible, 2-wire serial interface controls a variety of MAX8660/MAX8661 functions:

- The output voltages of V3–V7 are set by the serial interface.
- Each of the four step-down DC-DC converters (REG1-REG4) can be put into forced-PWM operation.
- REG3 and REG4 can be enabled by the serial interface or by a hardware-enable pin (EN34). See the REG3/REG4 Enable (EN34, EN3, EN4) section for more information.
- REG6 and REG7 are activated only by the serial interface.

The serial interface operates whenever V_{IN} is between V_{UVLO} (typically 2.40V) and V_{OVLO} (typically 6.35V). When V_{IN} is outside the I²C operation range, the I²C registers are reset to their default values.

The serial interface consists of a bidirectional serial-data line (SDA) and a serial-clock input (SCL). The MAX8660/MAX8661 are slave-only devices, relying upon a master to generate a clock signal. The master (typically the applications processor) initiates data transfer on the bus and generates SCL to permit data transfer.

 I^2C is an open-drain bus. SDA and SCL require pullup resistors (500 Ω or greater). Optional resistors (24 Ω) in series with SDA and SCL protect the device inputs from high-voltage spikes on the bus lines. Series resistors also minimize cross-talk and undershoot on bus signals.

The Marvell PXA3xx specification contains an extensive list of registers for various functions, not all of which are provided on the MAX8660/MAX8661. The list in Table 9 is a subset of the Marvell list as it relates to functions included in the PMIC. Even though the MAX8660/MAX8661 use a subset of the specified registers, they acknowledge writes to the entire register space (0x00 to 0xFF).

In Marvell PXA3xx applications, the pullups are typically to VCC_IOx.

Data Transfer

One data bit is transferred during each SCL clock cycle. The data on SDA must remain stable during the high period of the SCL clock pulse. Changes in SDA while SCL is high are control signals (see the *START and STOP Conditions* section for more information).

Each transmit sequence is framed by a START (S) condition and a STOP (P) condition. Each data packet is 9 bits long; 8 bits of data followed by the acknowledge bit. The MAX8660/MAX8661 suport data transfer rates with SCL frequencies up to 400kHz.

MAX8660/MAX8660A/MAX8660B/MAX8661

Table 9. I²C Registers

 	 									
SGO 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	 		 	 	++++++					
0 0 0 0	0 1 0 8 0	0 1 0 00 0			0 1 0 8 0 0	0 0 0 0 0				
0 00 0	0 00 0	0 0 0	0 00 0	0 98 0	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	0 0 0 0	0 0 0 0 0 0	0 0 0	0 0 0 0	000000000000000000000000000000000000000
+++++	000 0	000 0	000000000000000000000000000000000000000	000 0	000000000000000000000000000000000000000	000000000000000000000000000000000000000	000000000000000000000000000000000000000	000000000000000000000000000000000000000	0 0 0 0	0 0 0 0
								tage - See Table	14396 See Table	HD3
								N V Voltage	N V Voltage	N
Default Default	Default Default	Default Default Default	Default Default Default Default	Default Default Default Default	Default Default Default Default Default	Default Default Default Default Default	Default Default Default Default Default	Default 0	Default 0	Default 0 ARDA
Default		Default Default	Default Default Default	Default Default	Default Default Default Default	Default Default Default Default	Default Default Default Default Default	Default 0	Default 0	Default 0 ARDA
Default 0 0 0	Default 0 0 0 Default 0 0 0	Default 0 0 0 Default 0 0 0	Default 0 0 0 Default 0 0 0 Default 0 0 0	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default R R R	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0 R R R Default R R R	Default 0 0 0	Default 0 0	Default 0 0 0 VT Voltage	Default 0 0 VY Voltage Default 0 0 ARD4 ARD3
ш ш	Default 0 0 0	Default 0 0 0 0	Default 0 0 0 0 Default 0 0 0 0	Default 0 0 0 0 Default 0 0 0 0 BF R R BF R	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0	Default 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0	Default 0 0 0 0 Default 0 0 0 0 Default 0 0 0 0 Default 0 0 0 Default 0 0 0 Office of the state of the s	Default 0 0 0 VY Voltage—See Table 13 Default 0 0	Default 0 0 0 ARD4 ARD3 -
	Default 0 0 0	Default 0 0 0 R R R R R R	Default 0 0 0 R R R R Default 0 0 0	Default 0 0 0 Default 0 0 0 R R R R	Default 0 0 0 R R R R Default 0 0 0 Default 0 0 0	Default 0 0 0 Pofault 0 0 0 Default 0 0 0 Pofault 0 0 0 R R R R	Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0 Default 0 0 0	Default 0 0 0	Default 0 0 0 Default 0 0 0	Default 0 0 0 0 ATVORtage—See Table 13 ARB4 ARB3 —

High-Efficiency, Low-IQ, PMICs with Dynamic Voltage Management for Mobile Applications

R means these data locations are designated reserved in the Marvell PXA3xx specification.

Note: The MAX8660/MAX8661 acknowledge attempts to write to the entire address space from 0x00 to 0xFF, even though only a subset of those addresses actually exist in the IC.

 $^{^{\}star}$ These registers are accessed by the power R C bus of the Marvell PXA3xx processor.

^{**} Maintain these bits at their default 0 value for the MAX8661

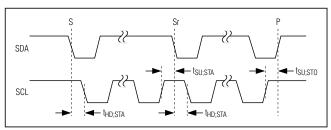


Figure 8. START and STOP Conditions

START and STOP Conditions

When the serial interface is inactive, SDA and SCL idle high. A master device initiates communication by issuing a START condition. A START condition is a high-to-low transition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA, while SCL is high (Figure 7).

A START condition from the master signals the beginning of a transmission to the MAX8660/MAX8661. The master terminates transmission by issuing a not-acknowledge followed by a STOP condition (see the Acknowledge Bit section for more information). The STOP condition frees the bus. To issue a series of commands to the slave, the master may issue repeated start (Sr) commands instead of a stop command in order to maintain control of the bus. In general, a repeated start command is functionally equivalent to a regular start command.

When a STOP condition or incorrect address is detected, the MAX8660/MAX8661 internally disconnect SCL from the serial interface until the next START condition, minimizing digital noise and feedthrough.

Acknowledge Bit

Both the master and the MAX8660/MAX8661 (slave) generate acknowledge bits when receiving data. The acknowledge bit is the last bit of each 9-bit data packet. To generate an acknowledge (A), the receiving device must pull SDA low before the rising edge of the acknowledge-related clock pulse (ninth pulse) and keep it low during the high period of the clock pulse (Figure 9). To generate a not acknowledge (A), the receiving device allows SDA to be pulled high before the rising edge of the acknowledge-related clock pulse and leaves it high during the high period of the clock pulse.

Monitoring the acknowledge bits allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master should reattempt communication at a later time.

Slave Address

A bus master initiates communication with a slave device (MAX8660/MAX8661) by issuing a START condition followed by the slave address. As shown in Figure 10, the slave address byte consists of 7 address bits and a read/write bit (R/W). After receiving the proper address, the MAX8660/MAX8661 issue an acknowledge by pulling SDA low during the ninth clock cycle. Note that the R/W bit is always zero since the MAX8660/MAX8661 are write only.

The Marvell PXA3xx processor supports 0x68 (SRAD = GND) as the I^2C slave address.

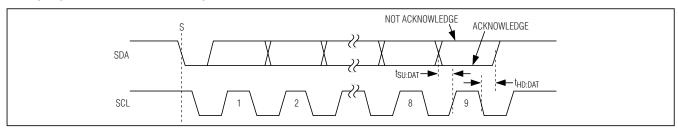


Figure 9. Acknowledge Bits

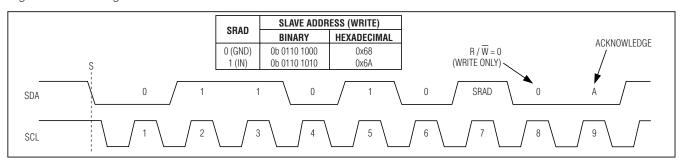


Figure 10. Slave Address Byte

Table 10. DVM Voltage-Change Register (VCC1, 0x20)

REGISTER ADDRESS	REGISTER NAME	ВІТ	NAME	FUNCTION	
		7	V5 (VCC_MVT) voltage select: 0—Ramp V5 to voltage selected by MDTV1 (default) 1—Ramp V5 to voltage selected by MDTV2		
		6	MGO	Start V5 (VCC_MVT) voltage change: 0—Hold V5 at current level (default) 1—Ramp V5 as selected by MVS	
		5	SVS	V4 (VCC_SRAM) voltage select: 0—Ramp V4 to voltage selected by SDTV1 (default) 1—Ramp V4 to voltage selected by SDTV2	
0x20	VCC1	4	SGO	Start V4 (<i>VCC_SRAM</i>) voltage change: 0—Hold V4 at current level (default) 1—Ramp V4 as selected by SVS	
		3	R	Reserved	
		2	R	Reserved	
			1	AVS	V3 (VCC_APPS) voltage select: 0—Ramp V3 to voltage selected by ADTV1 (default) 1—Ramp V3 to voltage selected by ADTV2
		0	AGO	Start V3 (VCC_APPS) voltage change: 0—Hold V3 at current level (default) 1—Ramp V3 as selected by AVS	

I²C Write Operation

The MAX8660/MAX8661 are write-only devices and recognize the "write byte" protocol as defined in the SMBus specification and shown in section A of Figure 11. The "write byte" protocol allows the I²C master device to send 1 byte of data to the slave device. The "write byte" protocol requires a register pointer address for the subsequent write. The MAX8660/MAX8661 acknowledge any register pointer even though only a subset of those registers actually exists in the device. The "write byte" protocol is as follows:

- 1) The master sends a start command.
- 2) The master sends the 7-bit slave address followed by a write bit.
- The addressed slave asserts an acknowledge by pulling SDA low.
- 4) The master sends an 8-bit register pointer.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a data byte.
- 7) The slave updates with the new data.
- 8) The slave acknowledges the data byte.
- 9) The master sends a STOP condition.

In addition to the write-byte protocol, the MAX8660/ MAX8661 recognize the multiple byte register-data pair protocol as shown in section B of Figure 11. This protocol allows the I²C master device to address the slave only once and then send data to multiple registers in a random order. Registers may be written continuously until the master issues a STOP condition.

The multiple-byte register-data pair protocol is as follows:

- 1) The master sends a start command.
- 2) The master sends the 7-bit slave address followed by a write bit.
- 3) The addressed slave asserts an acknowledge by pulling SDA low.
- 4) The master sends an 8-bit register pointer.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a data byte.
- 7) The slave updates with the new data.
- 8) The slave acknowledges the data byte.
- 9) Steps 5 to 7 are repeated as many times as the master requires. Registers may be accessed in random order.
- 10) The master sends a STOP condition.

Table 11. Serial Codes for V3 (*VCC_APPS*) and V4 (*VCC_SRAM*) Output Voltages

REGISTER ADDRESS	REGISTER NAME	DATA BYTE	OUTPUT VOLTAGE (V)*
		0x00	0.725
		0x01	0.750
		0x02	0.775
		0x03	0.800
		0x04	0.825
		0x05	0.850
		0x06	0.875
		0x07	0.900
		0x08	0.925
		0x09	0.950
		0x0A	0.975
		0x0B	1.000
	[0x0C	1.025
		0x0D	1.050
		0x0E	1.075
		0x0F	1.100
		0x10	1.125
		0x11	1.150**
	ADTV1 ADTV2	0x12	1.175
		0x13	1.200
0x23		0x14	1.225
0x24		0x15	1.250
0x29	SDTV1	0x16	1.275
0x2A	SDTV2	0x17	1.300
		0x18	1.325
		0x19	1.350
		0x1A	1.375
		0x1B	1.400 (default)*
		0x1C	1.425
		0x1D	1.450
		0x1E	1.475
	_	0x1F	1.500
		0x20	1.525
		0x21	1.550
		0x22	1.575
	_	0x23	1.600
		0x24	1.625
		0x25	1.650
		0x26	1.675
		0x27	1.700
		0x28	1.725
		0x29	1.750
		0x2A	1.775
		0x2B	1.800

Table 12. Serial Codes for V5 Output Voltage

REGISTER ADDRESS	REGISTER NAME	DATA BYTE	OUTPUT VOLTAGE (V)	
		0x00	1.700	
		0x01	1.725	
		0x02	1.750	
		0x03	1.775	
		0x04	1.800 (default)	
0x32	MDTV1	0x05	1.825	
0x33	MDTV2	0x06	1.850	
		0x07	1.875	
			0x08	1.900
				0x09
		0x0A	1.950	
			0x0B	1.975
		0x0C	2.000	

Table 13. Serial Codes for V6 and V7 Output Voltages

REGISTER ADDRESS	REGISTER NAME	DATA NIBBLE	OUTPUT VOLTAGE (V)			
		0x0	1.8 (default)			
		0x1	1.9			
		0x2	2.0			
		0x3	2.1			
	L12VCR	0x4	2.2			
		0x5	2.3			
					0x6	2.4
0x39		0x7	2.5			
		0x8	2.6			
		0x9	2.7			
		0xA	2.8			
			0xB	2.9		
		0xC	3.0			
		0xD	3.1			
		3.2				
		0xF	3.3			

^{*}Contact factory for other default voltages.

^{**}MAX8660B default voltage is 1.15V.

^{***}MAX8660/MAX8660A/MAX8661 default voltage is1.4V.

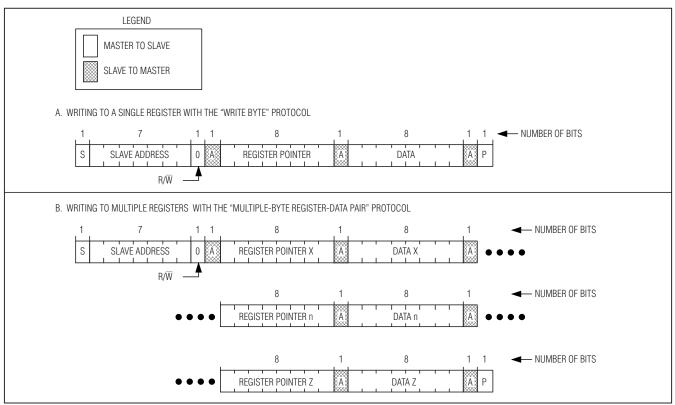


Figure 11. Writing to the MAX8660/MAX8661

Design Procedure

Setting the Output Voltages

The REG1 and REG2 regulators each have three preset voltages that are programmed with the SET1 and SET2 inputs. See the REG1 (VCC_IO) Step-Down DC-DC Converter and REG2 (VCC_IO, VCC_MEM) Step-Down DC-DC Converters sections for more information. V8 is fixed at 3.3V and cannot be changed.

V3-V7 are set by the I²C interface. See the I²C Interface section for more information. Note that while operating in forced-PWM mode with an input voltage greater than 4.3V, the minimum output voltage of REG3 and REG4 is limited by the minimum duty cycle. In forced-PWM mode, the minimum output voltage for REG3 or REG4 is:

$$V3_{MIN} = 0.167 \times V_{PV3}$$

 $V4_{MIN} = 0.167 \times V_{PV4}$

Note that the above minimum voltage limitation does not apply to normal-mode operation.

Inductor Selection

Calculate the inductor value (LIDEAL) for each of REG1 through REG4 as follows:

$$L_{IDEAL} = \frac{4 \times V_{IN} \times D \times (1 - D)}{I_{OUT(MAX)} \times f_{OSC}}$$

This sets the peak-to-peak inductor current ripple to 1/4 the maximum output current. The oscillator frequency, fosc, is 2MHz, and the duty cycle, D, is:

$$D = \frac{V_{OUT}}{V_{IN}}$$

Given LIDEAL, the peak-to-peak inductor ripple current is 0.25 x IOUT(MAX). The peak inductor current is 1.125 x IOUT(MAX). Make sure that the saturation current of the inductor exceeds the peak inductor current, and the rated maximum DC inductor current exceeds the maximum output current (IOUT(MAX)). Inductance values smaller than LIDEAL can be used to reduce inductor size; however, if much smaller values are used, peak inductor current rises and a larger output capacitance may be required to suppress output ripple. Larger

NIXIN

inductance values than L_{IDEAL} can be used to obtain higher output current, but typically require physically larger inductor size. Refer to the MAX8660 EV kit data sheet for specific inductor recommendations.

Input Capacitor Selection

The input capacitor in a step-down DC-DC converter reduces current peaks drawn from the battery or other input power source and reduces switching noise in the controller. The impedance of the input capacitor at the switching frequency should be less than that of the input source so that high-frequency switching currents do not pass through the input source.

The input capacitor must meet the input-ripple-current requirement imposed by the step-down converter. Ceramic capacitors are preferred due to their resilience to power-up surge currents. Choose the input capacitor so that the temperature rise due to input ripple current does not exceed approximately 10° C. For a step-down DC-DC converter, the maximum input ripple current is 1/2 of the output. This maximum input ripple current occurs when the step-down converter operates at 50% duty factor ($V_{IN} = 2 \times V_{OUT}$).

Refer to the MAX8660 EV kit data sheet for specific input capacitor recommendations.

Output Capacitor Selection

The step-down DC-DC converter output capacitor keeps output ripple small and ensures control-loop stability. The output capacitor must also have low impedance at the switching frequency. Ceramic, polymer, and tantalum capacitors are suitable, with ceramic exhibiting the lowest ESR and lowest high-frequency impedance.

Output ripple due to capacitance (neglecting ESR) is approximately:

$$V_{RIPPLE} = \frac{I_{L(PEAK)}}{2\pi \times f_{OSC} \times C_{OUT}}$$

Additional ripple due to capacitor ESR is:

VRIPPLE(ESR) = IL(PEAK) x ESR

Refer to the MAX8660 EV kit data sheet for specific output capacitor recommendations.

____ Applications Information

Power Dissipation

The MAX8660/MAX8661 have a thermal-shutdown feature that protects the IC from damage when the die temperature exceeds +160°C (see the *Thermal-Overload Protection* section for more information). To prevent thermal overload and allow the maximum load current on each regulator, it is important to ensure that the heat generated by the MAX8660/MAX8661 can be dissipated into the PC board. The exposed pad must be soldered to the PC board, with multiple vias under the exposed pad (EP) conducting heat to a ground plane.

The junction-to-case thermal resistance (θ_{JC}) of the MAX8660/MAX8661 is 2.7°C/W. When properly mounted on a multilayer PC board, the junction-to-ambient thermal resistance (θ_{JA}) is typically 28°C/W.

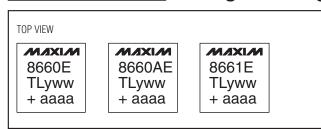
PCB Layout and Routing

Good printed circuit board (PCB) layout is necessary to achieve optimal performance. Conductors carrying discontinuous currents and any high-current path must be made as short and wide as possible.

Refer to the MAX8660 EV kit data sheet for an example of a good PCB layout. Place the bypass capacitors for each power input pair (IN to AGND, PV1 to PG1, PV2 to PG2, PV3, to PG3, and PV4 to PG4) as close as possible to the IC.

The exposed pad (EP) is the main path for heat to exit the IC. Connect EP to the ground plane with multiple vias to allow heat to dissipate from the device.

Package Marking



[&]quot;yww" is a date code.

__Ordering Information (continued)

PART	PIN-PACKAGE	OPTIONS
MAX8660AETL+	40 Thin QFN	V1: 2.5V, 2.0V, 1.8V V2: 2.5V, 2.0V, 1.8V V3: 1.4V (default) V4: 1.4V (default)
MAX8660BETL+	40 Thin QFN	V1: 3.3V, 3.0V, 2.85V V2: 3.3V, 2.5V, 1.8V V3: 1.15V (default) V4: 1.15V (default)
MAX8661ETL+	40 Thin QFN	No REG1 and REG7 V2: 3.3V, 2.5V, 1.8V V3: 1.4V (default) V4: 1.4V (default)

Note: All devices are specified over the -40°C to 85°C operating temperature range.

Chip Information

PROCESS: BICMOS

[&]quot;aaaa" is an assembly code.

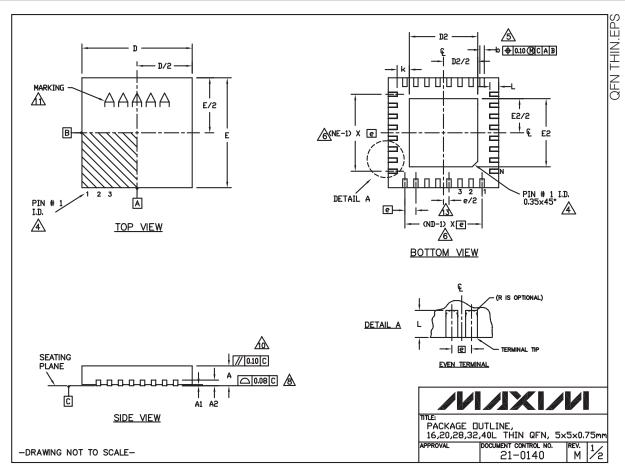
⁺Denotes lead-free packaging and marks pin 1 location.

⁺Denotes lead(Pb)-free/RoHS-compliant package.

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
40 TQFN	T4055-1	<u>21-0140</u>



Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

	COMMON DIMENSIONS														
PKG.	16	L 5	×5	21	20L 5x5		28L 5×5		32L 5x5			40L 5×5			
SYMBOL	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0	0.02	0.05	٥	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05
A2	0.20 REF.		0.20 REF.		0.8	0.20 REF.		0.20 REF.			0.20 REF.				
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.20	0.25	0.30	0.15	0.20	0.25
D	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10
Ε	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10	4.90	5.00	5.10
e	0.	80 B	SC.	0.65 BSC.		0.50 BSC.		0.50 BSC.			0.40 BSC.				
k	0.25	_	-	0.25	-	_	0.25	-	-	0.25	-	-	0.25	-	-
L	0.30	0.40	0.50	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.30	0.40	0.50
N		16		20		28		32		40					
ND		4		5		7		8		10					
NE	4		5		7		8			10					
JEDEC	1	WHHB		١	WHHC		WHHD-1		MHHD-5						

NOTES

- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- 4 THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- 🛕 DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.
- ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220, EXCEPT EXPOSED PAD DIMENSION FOR
- T2855-3, T2855-6, T4055-1 AND T4055-2.
- WARPAGE SHALL NOT EXCEED 0.10 mm.
- MARKING IS FOR PACKAGE DRIENTATION REFERENCE ONLY.
- NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- LEAD CENTERLINES TO BE AT TRUE POSITION AS DEFINED BY BASIC DIMENSION 'e', ±0.05.
- ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PIFREE (+) PKG. CODES.

-DRAWING NOT TO SCALE-

EXPOSED PAD VARIATIONS							
PKG.		D2		ES.			
CODES	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	
T1655-2	3.00	3.10	3.20	3.00	3.10	3.20	
T1655-3	3.00	3.10	3,20	3.00	3.10	3.20	
T1655-4	2.19	2.29	2.39	2.19	2.29	2.39	
T165N-1	3.00	3.10	3.20	3.00	3.10	3.20	
T2055-3	3.00	3.10	3.20	3.00	3.10	3.20	
T2055-4	3.00	3.10	3.20	3.00	3.10	3.20	
T2055-5	3.15	3.25	3.35	3.15	3.25	3.35	
T2055MN-5	3.15	3.25	3.35	3.15	3.25	3.35	
T2855-3	3.15	3.25	3.35	3.15	3.25	3.35	
T2855-4	2.60	2.70	2.80	2.60	2.70	2.80	
T2855-5	2.60	2.70	2.80	2.60	2.70	2.80	
T2855-6	3.15	3.25	3.35	3.15	3.25	3.35	
T2855-7	2.60	2.70	2.80	2.60	2.70	2.80	
T2855-8	3.15	3.25	3.35	3.15	3.25	3.35	
T2855N-1	3.15	3.25	3.35	3.15	3.25	3.35	
T3255-3	3.00	3.10	3.20	3.00	3.10	3.20	
T3255-4	3.00	3.10	3.20	3.00	3.10	3.20	
T3255M-4	3.00	3.10	3.20	3.00	3.10	3.20	
T3255-5	3.00	3.10	3.20	3.00	3.10	3.20	
T3255N-1	3.00	3.10	3.20	3.00	3.10	3.20	
T4055-1	3.40	3.50	3.60	3.40	3.50	3.60	
T4055-2	3.40	3.50	3.60	3.40	3.50	3.60	
T4055N-1	3.40	3.50	3.60	3.40	3.50	3.60	
T4055MN-1	3.40	3.50	3.60	3.40	3.50	3.60	

PACKAGE DUTLINE, 16,20,28,32,40L THIN QFN, 5×5×0.75mr

₹EV. 21-0140

Revision History

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
2	8/09	Added MAX8660B and automotive part options, and replaced Intel references with Marvell	1, 2, 3, 5, 6, 7, 10, 11, 19–34, 36, 37

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.